

## Index

### a

- Abbe, Ernst Karl 1
- Abbe theory of imaging 54–57, 162, 409*f*, 500
- aberration balancing, principle of 117
- aberration-compensated instruments 752
- aberration-corrected electron microscopes 51
- aberration-corrected imaging 309
- aberration-corrected instruments 693
- phase contrast of 85–86
- aberration-corrected JEOL 2200FS conversion 397*f*
- aberration-corrected microscopy 16, 61
- aberration-corrected spectrum imaging, in STEM 1180–1182, 1183*f*
- aberration-corrected systems, LEEM-based 677–682
- aberration-corrected TEM 81, 273, 294
- advantages 82
- area of diffraction in SAED 441
- for atomic holography 189–190
- electron diffraction pattern 443*f*
- Lentzen's contrast theory for 82
- resolution 1091–1094
- Scherzer's theory for 82
- aberration correctors 4–5, 335–336
- aberration-free probe 122
- ab initio* calculations 181, 1369–1371
- ab initio* phase determination techniques 445
- actin/alpha-actinin myofibrils 566
- Al-disordered  $\gamma$  matrix 267
- adsorbate-induced tip modification 560
- Advanced Light Source (ALS) 751
- Ag–Au nanoparticles 900
- Aharonov–Bohm effect 228
- Airy disc 119–120, 133, 428
- Alexa Fluor 488 (actin filaments) 566
- algebraic reconstruction technique (ART) 258
- alkaline earth oxide 398
- Al/Li intensity ratio 1093
- Al<sub>3</sub>Li L1<sub>2</sub> structure 1091–1092
- Al–Mg films 1101, 1103
- Al<sub>3</sub>Ni<sub>2</sub> 329
- Al–Ni atomic compositions 326
- Al/Ni reactive multilayer films 331–333
- Al-plasmons 205
- Al-rich diffraction experiments 329–331
- observations of morphological transients 331–333
- AlSm amorphous alloy 808
- alternative hypothesis 291
- $\gamma$ -alumina 112
- alumina–Cu interface 385
- ammonia tepida 730
- amorphous models of silicon clusters, speckle analysis of 415
- Ampère's circuital law 501
- amplitude contrast 88, 91
- amplitude contrast transfer function (ACTF) 90
- amplitude image, of reconstructed wave 160
- quantitative evaluation 160
- analytical solutions, to electron scattering equations 26–30
- anatase sol–gel 264
- anchor point 857
- angular distribution 127
- angular resolved X-ray photoelectron spectroscopy 1163
- anion-vacancy sites 388
- anisotropy 260
- annular bright-field (ABF) imaging 113

- annular dark-field (ADF) detectors 131, 262, 437
  - filtering effect of 132*f*
- annular dark-field (ADF) imaging system 109
  - ADF STEM 131
  - ADF TEM 265, 320
- annular detectors 130
- annular objective apertures 265–266
- anomalous absorption lengths 22
- antibody–antigen recognition binding 550
- anticontaminators 417
- antiferromagnetism 752
- apertureless near-field optical microscopy 507
- apertureless SNOMs 506
- arbitrary waveform generation laser 333–334
- Ar/CH<sub>4</sub> microwave plasma 1003
- ArcTan-function 161
- Argand diagram 444*f*
- Argand plot 70
- argon sputtering of tip 559
- Ar milling technique 483
- artificial phase modulations 160
- artificial supercrystal 77
- a-Si/c-Si interface 1217–1218, 1217*f*–1220*f*
- astigmatism 15–16
  - twofold 96
- atom column position measurement 294–295
- atomic diffusion 310
- atomic dimensions, of holography 180–197
  - aberration corrector and signal resolution 187–190
  - across STO/PTO/SRO interfaces 192*f*
  - adaptation of hologram geometry 184
  - of CCD camera 183–184
  - coherent aberrations, correction of 187–190
  - of ferroelectric fields 192
  - intrinsic fields 190
  - lateral resolution 183
  - optimum focus of lens 184–185
  - pixel number of CCDcamera 183–184
  - and polarization of unit cells 190
  - signal resolution 185–197
  - spatial frequencies 183
- atomic force microscopy (AFM) 3, 540, 693, 1046
- atomic impurity atoms 410
- atomic lateral resolution 187
- atomic resolution
  - 2D 255
  - 3D 273
  - imaging, at diffraction-limited resolution 438
  - spectrum imaging 1182
- atomic-resolution ETEM 376–380
  - aberration coefficients 377
  - advances 392
  - of alloy phase CuRu<sub>3</sub> 387
  - applications to biofuels 398–401
  - of butane oxidation over vanadyl pyrophosphate catalysts 388
  - camera chamber 378*f*
  - catalytic activity, study of 383–385
  - catalytically beneficial defects in 382
  - catalytically detrimental defects in 382
  - commercial production of 382
  - computer-controlled 377
  - of Cu–Ru nanoparticles 386–387
  - defect structures in 381–382
  - development of 377–379
  - drift compensation in 379
  - dynamic atomic resolution studies using 379
  - dynamic nanoparticle shape modifications in 383–388
  - dynamic oxidation states of 383–388
  - electron diffraction (ED) and 389
  - electronic structural changes, study of 384
  - electronic structures of promoted systems 383–388
  - EM columns in 378
  - evolution of structural changes at the atomic level 377
  - experimental procedures of 380–383
  - flow of gases in 378–379
  - gas–solid reactions in 381, 383
  - geometry of 377
  - image shift in 379
  - molecular drag pumps (MDP) of 378
  - noninvasive characterization of 380
  - for parallel “blank” calibration experiments 380
  - probing of gas–solid reactions 376
  - of Pt–Pd nanoparticles 397
  - pumping action in 378*f*
  - reactions in liquid phase 392–393
  - reactions in transition metal carbides 389
  - reduction–oxidation (redox) behavior in 385
  - *in situ* AC HAADF-STEM studies 397–398
  - structure of WC 390*f*, 389
  - studies with aberration correction 393–396
  - technological benefits of 391–392
  - turbomolecular pumps (TMP) of 378

- understanding of gas–solid reactions 380
  - understanding of kinetics and reaction processes 377
  - using electron-transparent samples 382
  - using ultrahigh-purity heater materials and sample grids 382
  - atomic resolution imaging, principles of
    - aberrations 84
    - contrast 84–86
    - electron wave field, representation of 83
    - enhanced contrast under negative spherical aberration conditions 87–91
    - exit-plane wave function 83–84
    - for fully aberration-corrected case 84
    - goal of 83
    - NCSI for higher sample thicknesses 91–94
    - resolution and point spread 83–84
  - atomic scattering factors 20
  - atom probe technique 3
  - atom probe tomography (APT) 260
    - alloy carbides, study of 822–824
    - alloy nitrides, study of 825–826
    - aluminum-based alloys, study of 821
    - basic principles 794–806
    - early stages of phase separation 820–828
    - GB segregation, study of 818–820
    - iron-based carbides, study of 821–822
    - linear defect segregation, study of 817–818
    - in material science 815–828
    - niobium nitride precipitation, study of 824–825
  - phase composition measurements 816–817
  - precipitation in alloys 826
  - specimen preparation 815–816
  - spinodal mechanism 826–828
  - state of art 813–815
  - steels, study of 821
  - atoms
    - as “alphabet” of nature 45
    - characteristic zones around 47–48, 48f
    - coordinates of, in an object 47
    - diffraction pattern of 48
    - Fourier transform of zones around 48
    - hypothetical point of 411
    - imaging experiment 46–49
    - interaction of electron with thin objects 72–73
    - magnetic hysteresis and spectroscopy of 557
    - neutral 411
    - normalized variance of 428
    - of a perfect crystal 47
    - propagation effect of electrons 74f
    - scattering from 411f
    - Si 412–413
    - of the unit cell 48
    - wave functions scattered from 414
  - Au atoms 139
  - Au-coated glass fiber 233
  - Auger electron emission microscopy (AEEM) 677
  - Au nanocatalysts 397
  - Au nanoparticle 352
  - Au particles, layering of 355–356
  - Au–Si eutectic pyramid, in a Si 692f
  - austenite–martensite interface, in Ti–Ni–Pd 1073–1077
  - automated diffraction tomography (ADT) 1369–1372
  - automated tripod polishing machine 486f
  - automatic noise estimation method 849
  - “averaged” microscope images 58
  - axial polarizations 805
  - aXis2000 771
  - azimuthal frequency 421
- b**
- back focal plane (BFP) 13–14
  - backscattered electrons and ions 628–634
  - backscattering 5
    - low-energy electron microscopy (LEEM) 676
  - back-thinning technique 477
  - bamboo tubes 1003
  - band excitation (BE) approach 553–554
  - band excitation nanothermal analysis (BE-NanoTA) 587–588
  - band excitation piezoresponse (force) spectroscopy (BEPS) 553
    - data acquisition and control methods 556f
  - band excitation scanning Joule thermal expansion microscopy (BE-SJThEM) 553–554
  - bandgap engineering 46
  - Bayesian techniques 259
  - beam broadening 135
  - beam excitation errors 23
  - beam-landing energies 618
  - BE-ESM decoupling, of electrochemical reactivity 581
  - belief propagation 855
  - bend contours 18
  - Bessel function 834
  - BESSY2 TXM 751–752
  - Betelgeuse star 420
  - Bethe, H. A. 19

- Bethe–Bloch formula 651–652  
 BF STEM imaging for electron tomography 262  
 BF TEM images  
   – diffraction contrast 266–267  
   – 3D reconstructions based on 264–265  
 BF TEM techniques 254, 261  
 bias-induced surface deformations 579  
   – detection of 574  
 bias-induced tip deflection 579  
 BiFeO<sub>3</sub>, column shape analysis in 141–144  
   – HAADF image of 144f  
 bimetallic (two-metal) nanosystems 386  
 Binnig, G. 505  
 biodiesel 398–401  
 biofuels 398–401  
   – energy-efficient nanocatalysts for 401  
 biological crystalline materials, preparation of 483  
   – ultramicrotomy 485–486  
 biological electron microscopy 1304–1306  
 biological tomographic techniques  
   – basic basic 1307–1309  
   – basic principles 1306–1307  
   – cellular morphology, study of 1321–1323  
   – contrast formation and imaging conditions 1318  
   – examples 1318–1325  
   – instrumentation 1313  
   – radiation damages 1316–1317  
   – resolution 1314–1316  
   – sample preparation 1309–1313  
   – sampling 1314–1316  
   – SARS-CoV infection and life cycle 1321, 1321f  
   – viral infection analysis 1320–1321  
   – viruses and macromolecular complexes 1323–1325  
   – whole cell analysis 1319–1320, 1319f  
 biomimetic fluoroapatite-gelatin system 171  
 biomineralization 171  
   – electric field in 175f  
 biopolymers 1337–1338  
 biprism 160, 162, 444  
   – X-FEG and optimum position of 193–197  
 biquadratic coupling 703  
 bismuth 721  
 bismuth LMIGs 713  
 Bi<sub>4</sub>W<sub>2/3</sub>Mn<sub>1/3</sub>O<sub>8</sub>Cl 294  
 Bloch wave approach, to imaging 19, 24–25  
   – dynamical scattering 134  
   – image stimulation 140  
 Bloch wave coefficient 24–25  
 Bloch wave formalism 90  
 block copolymers 1349, 1349f, 1354, 1357  
 B<sub>2</sub> NiAl, diffraction rings of 328, 332  
 B/N ratios 297  
 Boersch effects 314  
 Bohr Magneton, magnetic phase shift by 186–187  
 Bragg angle 16–17, 35  
 Bragg condition, in numerical multibeam approaches 31  
 Bragg equation 16  
   – reciprocal space version of 21  
 Bragg geometry 16  
 Bragg reflections of speckles 411–417  
 Bragg-scattered beams 262  
 Bravais cell 892  
 bright-atom contrast 91–92  
 bright-atom contrast conditions 94  
 Bright field image, of Ti foil 19f  
 bright-field phase contrast image 130  
 bright-field TEM 271  
   – images 225f  
 brightness, defined 314  
 bright spots 406  
 broad ion beam (BIB) systems 662  
 built-in potential, of pn junction 268  
 bulk heterojunction (BHJ) 1249, 1250f  
 bulk metallic glasses (BMGs) 1098  
 bullet morphology 263  
 Burgers vector 39  
   – for pure edge dislocation 39  
   – of a screw dislocation 39  
 Burgers vectors 1072
- c**  
 Cadmium selenide quantum dots, phasing of 464–469  
 Ca<sub>0.95</sub>La<sub>0.05</sub>TiO<sub>3</sub>/CaTiO<sub>3</sub> bilayer 1182  
 calcium–copper titanate 579  
 Cambridge Scientific Instruments Mark 1 “Stereoscan” 615  
 CAMECA NanoSIMS 50, 721–724, 723f  
 cantilever detection 545–546  
 cantilever sensors, for optical detection 546  
 cantilever system 507, 520, 550  
 capacitive tip–surface force 575  
 carbon-arc plasma generator 1010  
 carbon atomic chains 1035–1037  
 carbon-based BHJ photoactive layers, contrast creation in  
   – conductive atomic force microscopy (cAFM) 1257–1259  
   – electron tomography of PSCs 1259–1263  
   – energy-filtered transmission electron microscopy (EFTEM) 1255–1256

- scanning transmission electron microscopy (STEM) 1253–1254
- carbon beads 1007
- carbon-coated TEM grid 489, 660
- carbon-film-coated TEM grid, depositing 1D nanostructures 962
- carbon nanocones (CNCs) 1009–1010
- carbon nanoform spatial distribution, in a cell 1015
- carbon nanoscrolls 1007
- carbon nanospheres 1013–1014
- carbon nanotubes (CNTs) 263, 971–973, 984–985, 988–990, 996
  - Au–Pd alloy composition islands 1002
  - cup-stacked 1005
  - electron microscopic imaging 998–1005
  - on free-standing structures 1000
  - helically coiled 1005
  - interface of Ti/CNT 1002
  - *in situ* evaluation of tensile loading of 1015–1016
  - via chemical vapor deposition (CVD) 1000
- carbon onionlike particles 1010
- carbon peapods 1020
- carbon spiroid 1011–1012
- Cartesian real-space dimensions 409
- catalytic turnover frequency (TOF) 399, 401
- cathodoluminescence (CL) method 384
  - spectra of Sb-promoted tin oxide nanocatalysts 385f
- cathodoluminescence 145
- cationic (Ce and Zr) atomic columns 893
- CBED pattern for GaAs 18
- C contamination 365
- CdS/CdTe heterojunctions 1228–1231
- CdSe nanocrystals 263
- Cd<sub>2</sub>SnO<sub>4</sub> 1221
- CdTe/CdS solar cells 1220–1227
- cellular electrophysiology 576
- central slice theorem 256
- Ce–Pt intermetallic compound 890
- CePt<sub>5</sub> stoichiometry 890–891
- ceramic oxide substrates 385
- ceria crystallite 888
- ceria-zirconia nanoparticles 892, 894f
- ceria-zirconia oxides 894, 895f
- cesium implantation 713
- C<sub>70</sub> fullerenes 1014, 1015f
- channeling theory 67–70
- charge-coupled device (CCD) cameras 50, 284, 335, 654
  - detection quantum efficiency (DQE) of 164
  - drift compensation 379
  - holography using 155, 162–163
  - image shift 379
- charge flipping (CF) algorithm 454
- chemical and electrolytic methods 478–479
- chemical-bath deposition (CBD) 1221
- chemical fixation 477
- chemical force microscopy (CFM) 1047
- chemical imaging of nanostructures 939–940
- chemically assisted ion beam etching (CAIBE) 483
- chemically modified graphene 999
- chemical reactions, visualization of 1023–1025
- chemical vapor deposition (CVD) 661
  - CVD-deposited gold conductors 662
- chi-square distribution 291–292
- chlorobenzene 1251, 1253f
- chromatic aberration 2, 15–16
  - correctors 4
  - effect of 16
  - function 60
- chromatic effects 111
- CIGS solar cells 1231–1235
- CIGS thin films 1232–1236
- classical optical microscopy 1
- cleavage technique 477–478
- close-spaced sublimation (CSS) 1221
- CM200 field emission gun (FEG) microscope 162
- C<sub>60</sub> molecules 1015, 1022
- CM30 Special Tübingen TEM 185
- Co, hexagonal-close-packed crystals of 242
- cobaltite system 1198–1204
- Co-based passivation layers 1166
- Co crystal 237
- coherence factor, defined 317
- coherence length, of speckles 418
- coherence volume, of speckle 421, 422f–423f
  - hollow-cone illumination for controlling 421
- coherent approximation 58
- coherent diffractive imaging (CDI) 437, 746
  - in an FEG microscope 440
  - angle between diffracted and forward beams 450
  - brief history 446–447
  - condenser aperture 440
  - contrast transfer function (CTF) in 445
  - of a crystalline specimen 445
  - electron beam crossover 440
  - electron probe in 440
  - field of view 449–450
  - of finite objects 445–461

- coherent diffractive imaging (CDI) (*contd.*)
  - image information 454–455
  - information transfer in diffraction pattern 445
  - nanoarea 439–443, 442*f*
  - noncrystallographic phase problem 443–445
  - OL aberrations 440
  - oversampling 447–449
  - phase retrieval algorithms 451–454
  - phasing experimental diffraction pattern 461–469
  - probe magnification 440
  - requirements on beam coherence 450–451
  - sampling frequency in a diffraction experiment 449–450
  - selected-area electron diffraction (SAED) 441
  - shape information of the nanometer-sized objects 455
  - simulation studies 455–461
  - spatial frequency 450
- coherent fluence 317
  - defined 315
- coherent Foucault imaging 224
- coherent illumination 254
  - image intensity distribution for 93
- coherent imaging 53–54
  - using STEM 129–133
- coherent interference speckles 407
- coincidence point 664
- cold field emission electron gun 13
- colossal magnetoresistance (CMR) 1179
- coma 15, 96
- communication theory 834
- complementary cathodoluminescence (CL) investigations 531
- complementary metal–oxide semiconductor (CMOS) technology 1042
- complex image wave 53
- computerized field ion microscopy 812
- condenser I, II, III 439–440
- condenser lenses, of STEM 115
- condensor lenses 13
- conductance atomic force microscopy (C-AFM) 1046–1047
- conductance imaging atomic force microscopy (CI-AFM) 997
- conductive atomic force microscopy (cAFM) 545, 1164, 1251
  - amplifiers 546
  - contrast creation in carbon-based BHJ photoactive layers 1257–1259
- confidence interval 297
- confocal optical microscopes 616
- conical dark field (CDF) imaging procedures 1088
- constant-current mode STM 505
- constant force measurement 507
- contact mode AFM 563–564
  - lateral resolution 565
- continuous imaging tunneling spectroscopy (CITS) 597
- continuous random network (CRN) 430
- contrast damping effects 160
- contrast delocalization 84
- contrast principle, of atomic resolution imaging 84–86
- contrast transfer function (CTF) 127
  - absolute 317
  - coherent 316–317
  - of coherent diffractive imaging (CDI) 445
  - of JEOL 2AC 2200FS conversion 396*f*
  - low-energy electron microscopy (LEEM) 675, 682
  - of SEM 623, 624*f*
- conventional heating holders 350
- conventional transmission electron microscopy (CTEM) 1251
- convergence angle
  - of the condenser II 439–440
- convergence angle cuts off, for contrast-transfer function 312–313
- convergent beam electron diffraction (CBED) patterns 438, 964
- convolution operator 15
- convolution product 51
- CO/O<sub>2</sub>/He gas column 356
- cooperative shear model (CSM) 1145
- copper(II)-phthalocyanine (CuPc) 1013
- copper–ruthenium (Cu–Ru) nanoparticles 386
- CoPtCr film 227
- CoSi<sub>2</sub> sublimates 691, 692*f*
- CoSm-particles 178*f*
- cost function 856
- Cottrell atmospheres 817
- Coulomb potential, of the nucleus 166–167
- cracking, of organometallic molecules 662
- Cramér–Rao lower bound (CRLB), concept of 285–287, 293–294
  - for optimization of the experimental design 300–303
  - for Poisson-distributed observations 287–288
  - standard deviation of estimates 294
- critical angle 503–504
- critical flow defects 1145

- crop circles 1005–1006  
 cross beam column 488  
 cross section of a particle, in FIB system 650–651  
 Crowther equation 260  
 Cr-rich alloys 823  
 crushed enamel deposition 493  
 cryo-electron tomography 1322*f*, 1348, 1355–1357  
 cryoimmobilized frozen-hydrated specimen 1303  
 cryoprotection 4  
 cryo-spectro-tomography 756  
 cryoultramicrotomy 486  
 crystal, Fourier coefficients for reciprocal lattice vectors of 167  
 crystal field splitting 1179  
 crystalline materials 887–888  
 crystalline Si (c-Si) solar cells 1213  
 crystallographic contrast 633–634  
 crystallography 181  
 – lattice cell parameters determination 1362–1365  
 – structure analysis 1365–1369  
 $C_s$  corrector 440  
 c-Si/a-Si:H interface, atomic structure and electronic properties of 1215–1220  
 CS plane defects 388  
 CSS-grown CdTe films 1220  
 $C_{60}$ @SWCNT peapods 1020  
 Cu-alloy panel 349  
 Cu-based pillars 1130  
 Cu diffusion, profile of 385  
 Cu electrodeposition, using TEM 357–358  
 Cu-In-Ca-Se material 1235–1238  
 Cu/(In,Ga) ratio 1236  
 Cu(In,Ga)Se<sub>2</sub> films, chemical fluctuation-induced nanodomains in 1238–1242  
 Cu-K $\alpha$  radiation 17  
 Cu metal nanoparticles 385  
 Cu nanoparticles 266  
 Cu-poor Cu-In-Ca-Se material 1235  
 Cu-poor domains 1238, 1242  
 cup-stacked CNTs 1005  
 Cu-rich CIGS samples 1232  
 Cu-rich domains 1242  
 current–voltage ( $I$ – $V$ ) characteristics  
 – of an electromigration process 348*f*  
 – of N-doped carbon nanotubes (CNTs) 349  
 – of TEM 347  
 curtain effect 658–659  
 CuRu<sub>3</sub> superlattice 387*f*, 388  
 custom-built soft X-ray STXMs 753  
 Cu TEM grids 326  
 Cu<sub>x</sub>Se crystals 1232–1235
- d**  
 dahlielike aggregate 1009  
 damage-free atomic-scale sculpting, of graphene 351  
 damages, SEM 640–642  
 damping envelope 58  
 damping factor 127  
 2D amplitude-phase spectrogram 581  
 dark-field contrast 675  
 dark-field imaging 197, 673  
 dark field transmission electron microscopy (DFTEM) 1089  
 dark spots 406  
 Darwin–Howie–Whelan equations 19, 22, 26  
 data processing electronics, SPM-based 550–551  
 3D biological structures 254  
 DC-biased vibrating cantilever 576  
 3D chemical mapping (spectrotomography) 775–777  
 1D/2D/3D metrology 1155  
 deblurring 53  
 de Broglie wavelength 502  
 Debye-Waller factor 20  
 deconvolution algorithm 554  
 deconvolution filter 53  
 decoupling topography  
 – dual-pass methods 572–573  
 – modulation approaches 573–574  
 – phase and amplitude 574  
 – through different mechanical degrees of freedom 574  
 defect-free crystal 424  
 defect-free ideal crystals 90  
 defect images 37–42  
 – definition 37  
 – at a dislocation core 37  
 – dislocation diffraction contrast 39  
 – and displacement fields 38  
 – Fourier coefficients of distorted lattice potential 38  
 – at free surface of a crystal foil 37  
 – simulations 41  
 – at a stacking fault 37  
 – theory 38–41  
 – for two-beam orientation 39  
 defect phase-shift matrices 41  
 defocus aberration of lens 84  
 – optimal contrast 92

- defocused Fresnel image. 168
- defocus parameters 84
- defocus propagator 66
- degree of crystallinity 1338
- degree of spatial coherence 164
- delta-function 15
- delta functions 412
- depletion zone 636
- depth-dependent phase shift 91
- depth sectioning 135–140
- depth-sectioning tomography 273
- detection quantum efficiency (DQE), of CCD 164
- detector function ( $D$ ), 131
- detector system, of SPM 545–547
- deterministic mesoscopic switching mechanisms 581
- device under test (DUT) 505
- $dF/dz$  characteristic, of force–distance curve 508
- 3-D finite element analysis (FEA) 1141
- 3D Fourier space, of object 256
- DFT calculation 166–167
- diamond lapping films 484
- 10,10'-dibromo-9,9'-bianthryl 1042
- 6,11-dibromo-1,2,3,4-tetraphenyltriphenylene 1042
- $d_2I/dV_2$  (vibrational) imaging, in STM 597
- difference map (DM) algorithm 454
- differential operator 23
- differential phase contrast (DPC) microscopy 222
  - STEM 224
  - “summed image DPC” approach 224
- differential phase residual (DPR) 260
- diffracted beams (diffraction aperture) 13
- diffracted disk 30
- diffraction channeling effect 92
- diffraction contrast, in HAADF images 262
- diffraction contrast TEM images 266–267
- diffraction contrast tomography 266–268
- diffraction experiment 48–49
- diffraction geometries, in TEM 11, 16–18
- diffraction intensity
  - mapping of 437
- diffraction pattern 15
- diffraction wave function 409
- diffraction pattern 60, 196
  - of conventional intensity image 156
- diffuse scattering, of speckles 410
- digital diffraction pattern (DDP) 888, 890
  - of ceria-zirconia crystallite 893
  - identification of a vacancy 900
  - reflections in 892
    - from superlattices 899–900
- DigitalMicrograph™ 426
- digitization, of reconstructed wave 162–163
- dimpling 476–477
- diode-pumped YAG amplifiers 334
- dip-pen lithography 522
- Dirac delta-function 15
- Dirac equation 83
- Dirac’s bra-ket notation 21
- direct Fourier reconstruction 256
- “direct-knock-on” processes 709
- direct methods 290, 294
- direct methods, of sample preparation for TEM 475–493
  - Ar milling technique 483
  - beam-induced heating 483
  - biological crystalline materials 483
  - chemical and electrolytic methods 478–479
  - chemically assisted ion beam etching (CAIBE) 483
  - cleavage technique 477–478
  - combination of different methods 491–493
  - cross-section TEM samples of multilayer structures 481
  - Cu–Cr/Mo–C 479
  - detrimental effect of ion beam sputtering 482
  - electron-transparent specimens 478
  - focused ion beam milling 488–491
  - heterostructure systems 479
  - ion beam milling 479–483
  - liquid nitrogen (LN<sub>2</sub>) cooling 483
  - mechanical thinning 480
  - mechanical wet polishing 484
  - polycrystalline Cu specimen 479, 479f
  - preferential thinning 481
  - preliminary preparation technique 475–477
  - radiation-induced defect agglomeration or segregation 483
  - reactive ion beam etching (RIBE) 483
  - reactive ion techniques 483
  - single- or double-sector thinning 480
  - Si semiconductor device TEM specimens 483
  - Si/SiGe heterostructure 481–483, 481f
  - thin slice of material by chemical dissolution 478
  - tripod polishing method 483–485
  - ultramicrotomy 485–486, 487f–488f
  - Yb/Si specimen preparation 478
- direct replicas 474



- direct space 1336
- discrete algebraic reconstruction technique (DART) 271
- discrete tomography 258
- dislocation imaging
  - network, 3D representation of 267
  - STEM MAADF mode for 268
- dislocation motion 310
- dispersion relations 25
- displacive transformation-induced APB 1085
- distance-dependent spectroscopy 561
- distortions 15
- divinyl benzene (DVB) 769
- 4D microscopy 5
- 3D morphology 253
- DNA–CNT complex 1042
- dopant concentration 170
- dopant-selective etching, on TEM specimens 1161–1163
- doped poly-Si 1164
- doped semiconductors, electric fields in 170–171
- double acquisition methods 849–850
- double-beam interferometry technique 579
- double-pass methods 572–573
- double-walled carbon nanotubes (DWCNTs) 999–1000
- 2D projection effect 199
- 3-D reconstruction
  - of human body 254
  - nanoparticle 272f
  - of surfaces 855
- dual-AC resonance tracking (DART) method 553
- dual-axis tomography 260
- Dual Beam 367
- dual-beam column 488
- dual-beam system 664–666, 665f
- dynamical diffraction, in Z-contrast imaging 134–135
- dynamical extinction distance 69
- dynamic diffraction theory 19–42, 630
  - defect images 37–42
  - examples of computations 26–37
  - perfect crystal theory 21–25
- dynamic electron energy loss spectroscopy 389–391
  - study of nanoparticle systems 389–391
- dynamic grain growth 1101
- dynamic nanoparticle shape modifications 383–388
- dynamic oxidation states 383–388
- dynamic SIMS 711
- dynamic transmission electron microscopy (DTEM)
  - aberration correctors 335–336
  - aberrations 313
  - applications of 324–333
  - base microscope 320–323
  - brightness property 314
  - Child–Langmuir effect 338
  - coherent fluence 315–316
  - convergence angles 311–312, 319
  - current performance of single-shot 323–324
  - developing a 320–324
  - difference between ignition and snapshot image 329–331
  - diffraction results 327–329
  - dynamical image contrast formation 323–324
  - electron–electron scattering problem 319
  - electron optics and column sections 321
  - FEG brightness 319
  - fundamental wavelength 322
  - future developments for 333–339
  - inhomogeneous scattering effects 313
  - line defects (dislocations) 323
  - longitudinal space charge effects 315
  - novel electron sources 338–339
  - physical effects influencing properties 314
  - pixel intensity 323
  - planar defects (stacking faults) 323
  - pulse compression 339
  - pulse duration 319
  - pump-probe experiments 322
  - related quantity emittance 314–315
  - of RMLF samples 326
  - schematic representation 321f
  - single-shot 313
  - *in situ* continuous-flow fluid stage 337
  - space charge effects 313
  - spatiotemporal coherence 313
  - Ta disk photocathode 320
  - time resolution trade-offs 316–320
  - time-resolved studies using 311–320
  - UV laser pulse 320–321
- Dyson, Freeman 539
- e**
- Ehrenberg-Siday-Aharonov-Bohm-(ESAB-) effect 173
- Eigen frequencies 508
- eigenvalues 25
- Einstein model 140
- Einzel type lens 618
- elastic energy loss 651

- elastic scattering process 21, 23
- electrically modulated SPM modes 574
- electric-field-dependent studies 1287
- electric fields, evaluation using holography
  - biom mineralization in 171, 175f
  - of ferroelectric fields 192
  - intrinsic electric fields 169–173
  - phase modulation 170
  - structure potentials 166–169
- electric fields, in biological objects 171–173
- electric fields, in doped semiconductors 170–171
- electric force microscopy (EFM), principle of 513
- electric phase shift 173
  - at an interface between  $\text{LaAlO}_3$  and  $\text{SrTiO}_3$  186
  - on  $\text{BaTiO}_3$  grown on  $\text{SrTiO}_3$  186
  - by elementary charges 185–186
  - of a sphere 178f
  - vs magnetic phase shift 176–180
- electrochemical polishing 477
- electrochemical SPMs 545
- electrochemical strain microscopy (ESM) 539
- electromechanical coupling 582
- electromechanical coupling coefficients 579
- electromigration processes 347, 348f
- electron backscatter diffraction patterns 634–635
- electron backscattering diffraction (EBSD) 437
- electron beam 13
- electron beam–induced conductivity (EBIC) 635–636
  - imaging of a p–n junction 637f
- electron-beam-induced-current (EBIC) 145, 528
  - nano 529
- electron beam lithography 364
- electron biprism, holography using 154–157
- electron channeling 67–70
  - through atom columns with different mass densities 68f
- electron diffraction channeling 90
  - nuclear-charge dependence of 96
- electron diffraction methods 1365–1369
- electron–electron scattering problem 319
- electron energy loss spectra (EELS) 281, 309
  - B and N K-edge 296
  - Hartree Slater edges 296
  - model-based quantification of 296–298
- electron energy loss spectrometer 13
- electron energy loss spectroscopy (EELS) 111, 115, 345, 1251
  - dynamic 389–391
  - imaging 131
- electron energy-loss spectroscopy (EELS) 270
- electron energy near-edge structure (ELNES) 1084
- electron gun, TEM 12, 12f
  - energy spread of 13
  - types 13
- electron holographic tomography 268–269
- electron holography 153, 437
  - perfect holographic scheme 153
- electronic interferometry 557
- electronic structures, of promoted systems 383–388
- electron-lattice thermalization 805
- electron microscope 2
- electron microscopy 50–51
  - for identifying carbon nanoforms 998–1016
- electron–phonon coupling 560
- electron ptychography 438
- electron scattering, in a TEM 17
- electrons per pixel area 317
- electron tomographic reconstructions, resolution of 255
- electron tomography (ET) 1089–1091, 1251
  - applications 261–264
  - history 253–255
  - imaging modes 259–261
  - “missing wedge” of information 259–261
  - of PSCs 1259–1263
  - quantification of 273–274
  - reconstruction using backprojection 256–259
  - theory 255–256
- electron-transparent silicon nitride windows 227
- electron-transparent windows 376
- electron tunneling
  - in correlated electron materials 560–562
  - STM 545
- electron wave, reconstruction of 156–157, 156f
  - as a complex array of data 157
  - as grayscale images 157
  - properties of 157–166
- electrostatic lattice potential 19
  - Fourier expansion of 20
- electrostatic micromanipulator 489
- electrostatic potential 73
- ellipticity of illumination 164
- elongation, of reconstruction 259

- embedding 477
  - empty reference hologram 160
  - energy-dispersive spectrometry (EDS) 1103
  - energy-dispersive X-ray (EDX) spectroscopy 255, 265, 270, 345
  - energy-efficient nanocatalysts, for biofuel synthesis 401
  - energy-filtered bright-field TEM image 232
  - energy-filtered transmission electron microscopy (EFTEM) 200, 265, 1089, 1251
    - atomic-resolution 376–380
    - for beam sensitive materials 271
    - contrast creation in carbon-based BHI photoactive layers 1255–1256
    - for 3D compositional mapping 255
    - elemental maps 270
    - environmental cells in 376
    - mapping mode 1013
  - energy-filtering spectrometers 417
  - energy function 856
  - energy-loss background intensity 270
  - energy loss near edge structures (ELNESs) 937
    - spectral information 1164
  - energy-loss tomograms 271
  - energy minimization, in stereo image matching 862
  - energy minimization-based matching algorithms
    - annealing with inverse temperature 864–865
    - cost function with mean field annealing 863–864
    - grid matching 865–866
    - Markov random field (MRF) framework 863
    - mean field annealing-based interaction 863
    - optimization process 865
    - sparse-grid concept 862–863
  - energy spread, of electron gun 13
  - environmental scanning electron microscope (ESEM) 524
  - environmental transmission electron microscopes (ETEMs) 5, 345
    - field emission gun (FEG) 382–383
    - as a nanolaboratory with multiprobe measurements 379
    - *in situ* 380, 382, 388
  - error reduction (ER) algorithm 452–453
  - ESEM/SPM hybrid systems 533
  - ESM imaging mode 581
  - estimators 284
  - ethylene glycol dimethylacrylate (EGDMA) 769
  - Euclidian metric 769
  - evanescent electromagnetic waves 506
  - evanescent microwave microscopy 588
  - evanescent wave, detection of 503–505
  - Everhart–Thornley secondary electron detector 625, 626f
    - scattering of visible light 626
  - Everhart–Thornley electron multiplier detector 652–653
  - Ewald sphere 17, 22, 30–32, 35, 38, 61, 76
  - exchange asymmetry 698
  - excitation coefficient 284
  - excitation error 25
  - exit face wave function 130
  - exit-plane wave field 84
  - exit-planewave function 83
  - exit wave reconstruction 59, 67
  - exit wave reconstruction methods 113
  - exothermic formation reactions, self-propagating 325–326
  - expectation-maximization (EM) 50
    - algorithm 849
    - HREM 50, 57
  - expectation model 291
  - experimental diffraction pattern, phasing procedures 461–469
    - CdS quantum dots 464–469
    - diffraction patterns and images 462–464
    - object domain error metric 468
    - object function reconstruction, from diffraction pattern 466–467
    - *R* factor during an iterative phase retrieval 468–469
  - experimental HREM
    - aligning microscope 60
    - interpretation of images 63–64
    - specimens 61–63
  - experiment–theory–design, interplay between 46f
  - exposure time 164
  - ex situ lift-out method 488–489
  - extended energy loss fine structure (EXELFS) studies 379, 937
  - extinction distances 22
  - extracellular matrix (ECM) protein 566
  - extraction replicas 474
- f**
- face-centered cubic (FCC) structure 967
  - F-actin cytoskeleton 566
  - Faraday cage 625
  - far-from-equilibrium nanolaminates 329

- fast lock-in sweep approach 553
- FeCrMoC steels 822
- Feenstra, R. A. 562
- Fe-Ferritin nanoparticles 899
- FEI Tecnai TF20-UT microscope 1213
- FEI Titan 80–300 “cubed” microscope 1093
- FEI TITAN 80–300 microscope 299
- FEI Titan TEM 233, 235
- Fe-Mn-based austenitic steels 1071
- FeMnC alloy 822
- Fe-Mn-C Hadfield steels 1071
- Fe-Mn-C steel 1073
- Fe-Mn-Si-Al grade steel 1071
- Fe-Mn-Si-Al TWIP steel 1073
- femtosecond spectroscopy 311
- Fermi degeneracy 316
- Fermi function, of semiconducting sample 504
- ferrimagnetic magnetite nanocrystals 245
- ferroelasticity 1273–1274
- ferroelastic perovskite LaAlO<sub>3</sub> 1280
- ferroelectric fields 192
- ferroelectric polymers 582
- ferroelectrics 580
- ferroic materials
  - amorphization and 1287–1290
  - domain boundaries 1280–1287, 1290–1295
  - domain patterns 1276–1280
- ferromagnetism 752
- Feynman, Richard 45
- fibers 1357
- fibroblasts, AFM cell studies of 565
- field curvature 15
- field effect transistors (FETs) 170
- field emission electron microscope 310
- field emission gun (FEG) 439
- field emission gun (FEG)-ETEMs 382–383
- field emission microscope (FEM) high resolutions 504
- field emission microscopy 2
- field emission source (FEG) 51
- field-enhanced ionization 617
- field evaporation 812
- field-free space 166
- field-free vacuum 167
- field ion microscope (FIM) 793
  - image interpretation 807–808
  - line defects 809–810
  - in material science 808–813
  - phase contrast 810–811
  - planar defects 810
  - point defects 808–809
  - three dimensional 811–813
- field ionmicroscopy (FIM) 2–3
- field of view, of reconstructed wave 161, 165
- field pulsing mode 803
- fifth-order correctors 109
- fine structures 937
- Fisher information, concept of 285
  - matrix 286–287
- Fisher information matrix 301
- fixed MRC-5 fibroblast cells 566
- flexible illumination system 316
- fluctuation electron microscopy (FEM) 405, 421–424
  - cartoon view of 429f
  - microdiffraction pattern 423
  - resolution 423
  - in terms of a focused STEM probe 423, 424f, 426
- fluid AFM 565
- fluorescence imaging 510
- fluorescence microscopy 1054–1055
- fluorescence quenching microscopy (FQM) 997, 1053–1054
- fluoroapatite-gelatin system 171
  - biocomposite 172
  - fractal growth in 172
  - mineralized macromolecules of 172
  - triple-helical protein fibers of gelatin 172
- flux-closed (FC)magnetic states 239
- focal-series reconstruction 290
- focused ion beam (FIB) system 3, 170
  - binary scattering and recoil 650
  - Coulomb potentials 651
  - cracking, of organometallic molecules 662
  - cross section of a particle 650–651
  - deposition of material 657, 661–662
  - detection of electron and ion signals 652–655
  - electronic collisions and 649
  - encasing of gold-covered lamella with platinum 658f, 659
  - energy loss 651–652
  - FIB-SEM dual-beam system setup 664–666, 665f
  - focusing of ion beam 646–647
  - gas-assisted etching (GAE) 656
  - imaging resolution 663–667
  - implantation 662–663
  - induced platinum deposition 659
  - interactions of ion with matter 648–649
  - interatomic potentials 649–650
  - level of localized control and precision 663
  - lift-out technique 660
  - LMIS and 645
  - microsampling 660–661

- milling technique using 655–657
  - nuclear energy loss 652
  - overlapping of beam 647–648
  - patterning capability 662
  - primary signals used 652
  - process of thinning 657
  - quantitative comparison with SEM 653*t*
  - reduced energy 651
  - rotatable grid holder 658
  - sample preparation 657–661
  - schematic diagram of 646*f*
  - screening length 650
  - SEM image 173*f*
  - sputtering process 656
  - TEM lamellae samples, preparation of 658
  - “top-angle cleaned” specimens 659
  - focused ion beam milling 480, 488–491
  - foraminifera 730
  - force-based multiple-probe SPMs 596
  - force-based SPM measurements 563–574
    - cell studies 565–566
    - contact mode 563–564
    - feedback loop 563
    - phase imaging 565
    - tapping (intermittent) mode 565
    - tip–surface contact area 563–564
    - force–distance spectroscopy 567–572
    - chemical functionalization of probe 570
    - colloidal forces 570–571
    - force-clamp methods 570
    - force–distance curves 569–571, 569*f*
    - generalization of 571
    - single-point force measurement 568–569
    - spectrum of tip–sample forces 569
    - structure–function relationships 570
  - force microscope in noncontact 513
  - force spectroscopy 567
  - force volume imaging 567
  - formalisms
    - in Bloch wave excitation 25
    - real-space 19
  - forward-scattering approximation 74–75
  - Foucault imaging 222–223, 222*f*
    - coherent 224
  - Fourier coefficient, of lattice potential 22
  - Fourier coefficients, for reciprocal lattice
    - vectors of crystal 167
  - Fourier coordinate 156
  - Fourier expansion of  $V(\mathbf{r})$  20
  - Fourier reconstruction methods 256
  - Fourier shell correlation (FSC) 260
  - Fourier space approach, to diffraction 21–23
    - in perfect crystal 47
  - Fourier transform
    - of an amorphous object 60
    - of the BFP 14–15
    - cadmium selenide quantum dots 465
    - of the exit wave 130
    - of exit wave function 443
    - of Gaussian probe after OL 441
    - of hologram 444
    - operations 888
    - wave function 409–410
  - Fourier transform/optical diffractogram (FFT/OD) 397
  - four-probe transport measurements 577
  - Frank loop plane 1094
  - Fraunhofer diffraction conditions 14–15, 443, 500
  - freeze fracture and etching 1350–1351
  - freeze fracture replicas 474
  - frequency-modulation atomic force microscopy (FM-AFM) 551
  - Fresnel holography 199
  - Fresnel imaging 222–223, 222*f*
    - fringe spacing 223
    - qualitative interpretation of 223
  - Fresnel propagator 24
  - fringe spacing, off-axis electron holography 234
  - fringe spacing, of reconstructed wave
    - 161–162, 164
    - from centerband 162
    - from sideband 162
    - for a weak pure phase object 162
  - frozen phonon method, of image simulation 140
  - frustrated total internal reflection 504
  - fullerene crystals (fullerites) 1013, 1020, 1020*f*, 1022, 1024*f*
    - *in situ* growth of 1035
  - full-field photoelectron microscopy (X-PEEM) 751–752
  - full-field transmission X-ray microscopy (TXM) 749–751
  - full width half maximum (FWHM), of probe 120, 128
- g**
- GaAs crystal structure 32
    - CBED pattern 33, 34*f*
  - GaAs wafer, EBIC on 636
  - Gabor, Dennis 45, 227
  - gadolinia-doped ceria 576
  - Ga/(In + Ga) ratio fluctuation 1242
  - Galilei, Galileo 499
  - Gallium (Ga) 645
  - gallium liquid metal ion guns (LMIGs) 713

- gamma distribution 431
  - GaN epilayer 267
  - GaN light-emitting device 531
  - GaN quantum wells 492
  - gas-assisted etching (GAE) 656
    - advantages 656
    - disadvantages 656
  - gas chemisorption, on nanoparticle surfaces 386
  - gas–nanocatalyst interface interactions, of ETEM 381, 383
  - gas nanoreactors 353–356
    - hydrogen storage materials 354–355
    - layering of Au particles on TiO<sub>2</sub> layer 355–356
    - SiN membranes and 353
  - Gatan Digital Micrograph 396
  - Gatan Image Filtering (GIF) system 1213
  - Gatan imaging filter 242*f*
  - Gatan PEELS/GIF system 379
  - Gaussian complex number plane, WPO of 85
  - Gaussian-distributed random speckle 430
  - Gaussian distribution 440
  - Gaussian electron source, resolved pixel for 164
  - Gaussian focus 117–118
  - Gaussian PDF 833–834
  - Gaussian regression analysis 103
  - generalized Rician PDF 835–836
  - geometric optimum probe 120
  - Gerchberg–Saxton (GS algorithm) 452
  - Ge<sub>1-x</sub>Sn<sub>x</sub>Te 1274
  - Gibbs free energy 1275
  - Ginzburg energy 1275
  - Glaser unit 59
  - glial cells, AFM cell studies of 565
  - glide shear plane defects 388
  - global fattening effect 1140
  - goniometers 96
    - tilting mechanism 260
  - grafting technique 522
  - grain boundary motion 1098
  - graph cuts 856, 872
  - graphene 2, 351–352, 1026–1028
    - defects in 1028
    - edges 1028–1030
    - electronic and bonding structure 1030
    - elemental analysis of 1030–1032
    - grain structure 1032
    - *in situ* growth of 1034
  - graphene sheets 464–465
  - Griffith theory 1145
- h**
- HAADF detector 115
  - Hall–Petch strengthening process 1071–1072
  - halogenated Pc molecules 1360
  - Halske 2
  - Handbook of Microscopy*, 503, 505
  - harmonic detection 574
  - Hartree Slater edges 296
  - H-bar technique 488–489
  - H-diluted NH<sub>3</sub> pretreatment 1215
  - He<sup>+</sup> ions (HIM) beam
    - of alumina powder grains 621, 622*f*
    - backscatter yield of 625
    - iSE1 and iSE2 components 625
  - He<sup>+</sup> ions (HIM) beam microscope 615, 620–621
  - Heisenberg principle of uncertainty 502
  - Heisenberg uncertainty product 316
  - herringbone-type carbon nanofibers (CNFs) 1009
  - Hertzian dipole moment 501
    - far- and near-field investigations of 501*f*
  - Hertzian dipoles 499
  - Hessian matrix of ln *P*, 286
  - H etching 1216–1220, 1217*t*, 1217*f*–1220*f*
  - hetero-bipolar transistor (HBT) 511
  - hexagonal-close-packed crystals, of Co 242
  - HgTe:CuTe-doped graphite paste 1221
  - high-angle annular dark-field (HAADF) imaging 109
    - probe intensity and 135
  - high-angle annular dark field (HAADF) scanning transmission electron microscopy (STEM) 4, 893–895, 898
    - of an La<sub>0.7</sub>Sr<sub>0.3</sub>MnO<sub>3</sub>–SrTiO<sub>3</sub> multilayer structure 299, 299*f*
    - characterization of columns 299, 300*f*
    - images 281
    - imaging at 30 and 60 kV 1025–1026
    - quantification of TiO and MnO columns 300
    - quantitative atomic resolution mapping using 298–300
    - statistical parameter estimation theory and 298
  - high-angle annular dark field (HAADF) TEM 312
    - incoherent 317
  - high-angle annular detector 131
  - high-angle (Rutherford) scattering 134
  - higher order aberrations 16
  - higher order Laue zones (HOLZ) 35
    - geometry of higher order 36*f*

- lines 11, 35
- high impact polystyrene 167
- high-magnetic field machines 540
- high-resolution electron microscopy (HREM) 50, 57, 437
  - of crystalline objects 75
  - experimental 60–64
  - image contrast and 437–438
  - quantitative 65–72
- high-resolution lab-based tomography 254
- high-resolution transmission electron microscopy (HRTEM) 281, 478, 1360–1361
  - image of nanowire 963, 966
- high T<sub>c</sub> superconductivity (HTCS) 1179
- high time resolution movies 334–335
- high-voltage electron microscopy 290
- high-voltage microscopes 2
- high-Z barrier materials 1166
- HIM Orion ZEISS 370
- hollow-cone DF tomography 264–266
- hollow-cone illumination 421
  - coherence volume of 421
  - dark-field images 427*f*
  - illumination tilt vector 426
- hologram, recording of 154–155, 155*f*
- holographic flux diagram of information 154*f*
- holographic tomography 171, 180
- holography 57, 66–67, 444
  - amplitude and phase image 198*f*
  - at atomic dimensions 180–197
  - dark-field 202–204
  - dark field reconstructions 200*f*
  - electric field investigation using 166–173
  - Fourier transform of the hologram 156
  - fringe patterns 155
  - geometric phase distribution 202
  - image-plane off-axis, using the electron biprism 154–157
  - for image retrieval 54
  - inelastic 204–209
  - interference pattern following superposition 154
  - magnetic field investigation using 173–180
  - phase contrast 168*f*
  - quantitative measurement of magnetic moments 244–246
  - reconstruction of electron wave 156–157
  - recording of hologram 154–155
  - tomography 199–202
  - using charge-coupled device (CCD) 155
- homogeneous bulging/swelling 1141

- Hooke, Robert 1
- horizontal field of view (HFOV) 616
- Hosaka's interleave method 573*f*
- HREM images of ceria-zirconia nanoparticles 892, 894*f*
- Huygens principle 500
- Huyghen's principle 54
- HV pulsing mode 803
- hybrid-input-output (HIO) algorithm 453
- hydrogenated Pd particles 355
- hydrogen storage materials 354–355
- hydroxyapatite collagen biosystem 171
- Hysitron picoindenter 1138

## i

- ideal experiment 46–49
- Iijima, Sumio 998
- illuminating electron wave function 443
- illumination coherence, of speckles 417–421
  - coherence length 418
  - spatial 419–421
  - temporal 418
- illumination intensity 418
- illumination section, of TEM 12*f*, 13
  - incoherent effects 57
- illumination tilt vector 426
  - dark-field conditions 428
- image restoration 53
- image stimulation
  - aberration-corrected images 140
  - Bloch wave method of 140
  - column shape analysis in BiFeO<sub>3</sub> 141–144
  - frozen phonon method 140
  - HAADF images 140
  - shape PCA analysis 141–143, 142*f*
- imaging experiment 49
  - advantages 50
  - significance 49–50
- imaging modes, in TEM 11, 16–17, 19
- imaging theory of Abbe 54–57, 162, 409*f*, 500
- impedance measurements, SPM-based 545
- implantation, FIB-induced ion 662–663
- impulse response function 51
- impurity-induced quantum wells 560
- incident angle of a wave 503
- incident plane wave 130
- incoherent HAADF-TEM imaging 317
- incoherent imaging 57–58
- incoherent imaging, using STEM 129–133
- indirect methods, of sample preparation for TEM 474
- indirect replicas 474

- inductively coupled plasma (ICP) sources 488
  - inductive moment 244
  - inelastic coherent patches 159–160
  - inelastic electron tomography 270–271
  - inelastic electron tunneling spectroscopy (IETS) 560
  - inelastic energy loss 651
  - inelastic filtering, of reconstructed wave 159–160
  - inelastic ion–electron collisions 649
  - infiltration embedding 477
  - infinite-impedance probe 577
  - information content, of reconstructed wave 165–166
  - infrared optical beam-induced current (OBIC) 1171
  - infrared optical beam-induced resistance change (IR-OBIRCH) 1171
  - infrared phonon frequency 410
  - in-line holography 66
  - in-plane dislocations 267
  - in situ* aberration-corrected electron microscopy observations
    - Pt–Pd nanoparticles 397, 399*f*
  - in situ* 2AC-EM 397
  - in situ* Ar ion polishing 490
  - in situ* electrochemical nucleation 357
  - in situ* ETEM 380, 382
  - in situ* gas and fluid TEM stages 336–338
  - in situ* high-temperature annealing 1014
  - in situ* hydrogen reduction 385
  - in situ* lift-out method 488
  - in situ* low-pass filter 266
  - in situ* micromanipulator 490, 491*f*
  - in situ* microscopy 5, 310
  - in situ* nanoindentation measurements 1098
  - of nanocrystalline Al thin films 1101
  - in situ* studies, by soft X-ray microscopy 777–780
  - in situ* TEM techniques
    - compression experiments 1125–1146
    - experiments 1100–1110
    - grain boundary dislocation dynamics 1110–1116
    - load control *vs* displacement control 1104–1110
    - special specimen stage design 1101–1102
    - specimen geometry and specimen preparation 1102–1104
    - tensile experiments 1117–1125
  - integrated circuits (ICs), optical inspection of 509
  - intensity variance 428
  - interaction, TEM 12*f*
  - interaction constant 24
  - interaction wave 69
  - interference fringe visibility, off-axis electron holography 233–234
  - interference phenomenon 408
  - intrinsic electric fields 169–173
  - inverse Fourier transform 54, 157
  - inverse temperature parameter 863
  - inversion of the imaging process 94–97
    - exit-plane wave function 95
    - steps in 95
    - tilted specimen yields 95–96
    - wave-function retrieval 95
  - ion-beam-based sputtering 728
  - ion beam milling 479–483
  - ion beam platinum deposition 662*f*
  - ion beams, source of 617
  - ion-generated secondary electron (iSE) 621
  - ionic screening 191
  - ion implantation 662–663
  - ion-induced deposition 662
  - ionization damages 4
  - ionization efficiency, of SIMS 712–713
  - ion milling 477
  - iron oxide–gold molecular assemblies 899
  - irradiation-sensitive alloys, modification of 492
  - islets of Langerhans 1319–1320, 1319*f*
  - iterated conditional mode (ICM) 855
  - iterative algebraic reconstruction algorithm 271
  - iterative algorithm 451–454
  - iterative “energy minimization –electron diffraction match” method 1367
  - iterative transformation algorithms (ITAs) 439
- j**
- Jackson’s “Classic Electrodynamics” 501
  - Jacobsen, Chris 769
  - Jahn-Teller distorted perovskite 1183
  - Janssen, Hans 499
  - JEOL 3010, 1101–1102
  - JEOL 2AC 2200FS conversion 396–397, 397*f*
  - JEOL 200CX 1104
  - JEOL 120CX microscope 12*f*
  - JEOL 200CX microscope 1101
  - JEOL2010F 1101–1102
  - JEOL 2010F electron microscope 440–441



JEOL 2010F TEM 1138  
 JEOL 3010/JEOL2010F microscope 1104

## k

Kaczér's microscope 542  
 Kelvin probe force microscopy (KPFM) 513,  
 514*f*, 549, 574–576  
 – of an electroceramic interface 578*f*  
 – charge injection and oxygen vacancy  
 diffusion 576  
 – DC and AC electric potentials 576  
 – electric potential 574–575  
 – electrostatic surface potential 575  
 – feedback loop 575  
 – frequency-modulated 575  
 – image formation 575  
 – LIA 575  
 – semiconductor and electroceramic devices,  
 study of 576  
 – solar materials study 576  
 – static potential 575  
 Kikuchi lines 11, 35, 37*f*, 635  
 kinematical approximation 443  
 kinematic approximation 167  
 kinematic interaction 181  
 kinematics of massive particles 315  
 kinetic energy 167  
 kinetic momentum 175  
 Kirkpatrick-Baez (KB) mirror 746  
 knock-on damages 4  
 Knoll, Max 2  
*K*-space 833, 849  
*k*-value, of dielectric 1168  
 Kwon, K.W. 464

## l

LaAlO<sub>3</sub>/SrTiO<sub>3</sub> multilayers 658  
 LaB<sub>6</sub> cathode 617  
 LaB<sub>6</sub> top-entry JEOL 4000EX microscope  
 1082  
 lacey carbon films 464  
 Lambert-Beer law 765  
 Lambert's cosine law 626  
 Landau free energy 1275  
 lanthanides 389  
 Laplacian operator 19, 75  
 large biological macromolecular complexes  
 1337  
 large-chamber scanning electron microscope  
 (LC-SEM) 855, 856*f*  
 – belief propagation matching 866–869  
 – graph cut matching 871–874  
 – local support window matching 869–871

– spectral information at different energy  
 levels 873–874  
 – stereo image acquisition 860–861  
 laser deflection technique 507  
 LASER-holography 199  
 laser illumination 805  
 lateral force microscopy 574  
 lateral phase space ellipse, rate of evolution at  
 315  
 lateral resolution, of reconstructed wave  
 161–162, 165  
 Laue geometry 16  
 Laue zones 61, 75  
 Lawrence Livermore National Laboratory  
 (LLNL) 311  
 lead zirconate titanate (PZT) 82  
 Leeuwenhoek, Antonij van 499  
 Leeuwenhoek, Antoni van 1  
 Lentzen's contrast theory 82  
 leukemia (RBL) cells, AFM cell studies of  
 565  
 Lewis acid sites 388  
 lift-out technique 488–489  
 – FIB system 660  
 light microscopy 84  
 likelihood function of parameters 288  
 likelihood ratio test 291–292  
 Lindhard, Scharff, and Schiott (LSS) formulae  
 652  
 linear approximation of atoms 181  
 linear image formation  
 – coherent imaging 53–54  
 – incoherent imaging 57–58  
 – at optimum defocus 58–59  
 – real imaging 51–53  
 – resolution 59–60  
 linear photoemission 313  
 lipid droplets (LDs), freeze fracture overview  
 of 474, 475*f*  
 liquid metal ion source (LMIS) 488  
 liquid metal ion sources (LMISs) 645  
 liquid nanoreactors 356–360  
 – Cu electrodeposition, using TEM 357–358  
 – imaging of *in situ* platinum nanocrystal  
 growth 359  
 – using silicon-based technology 356–357  
 liquid-nitrogen-cooled specimen holder  
 225–226  
 liquid nitrogen (LN<sub>2</sub>) cooling 483  
 LISICON 581  
 lithium-ion materials 581  
 liver endothelial cells, AFM cell studies of  
 565  
 living cells, high-resolution imaging of 565

- local support window (LSW) 855
- lock-in amplification 512
- lock-in amplifiers (LIAs) 551, 575, 597
- log-likelihood function 288
- long-range order 425
- Lorentz deflection angle 223
- Lorentz force 173
- Lorentz microscopy 233, 237, 239
  - applications 224–227
  - comparisons of fringe contrast with defocus 223
  - of a CoPtCr/alumina/Co magnetic tunnel junction 226f
  - electron diffraction patterns 221–222
  - fringe spacing 223
  - history of 221–222
  - imaging modes 222–224
  - interference fringes 221
  - low-temperature monoclinic phase 226
  - magnetic fringing fields 221
  - “magnetization ripple” contrast 223
  - monoclinic twin domains 226–227
  - out-of-focus images 225
  - and out-of-focus images in Fe and NiFe films 221
  - out-of-plane (OOP) component of magnetic field 225
  - in polycrystalline specimens 223
  - quantitative image interpretation 223–224
  - *in situ* magnetizing experiments 224
- Lorentz mode 162
- low-energy electron diffraction (LEED) 697
- low-energy electron microscopy (LEEM) 697
  - aberration correction optics 677, 679f, 682
  - adsorbate-covered regions 675
  - adsorption layers, study of 684–689
  - adsorption of impurities 687
  - agglomeration of low temperature-deposited layers 690
  - angle-limiting aperture 682
  - beam separators 679, 681
  - bright-field 675
  - cathode lens 682
  - CCD camera 681
  - contrast aperture 679–681
  - contrast transfer function 675, 682
  - diffraction contrast 675
  - double-channel plate-fluorescent screen detector 681
  - elastic backscattering 676
  - energies of Auger electrons 678
  - energy bandgap 674
  - energy filter 681
  - field-limiting aperture 680
    - growth of thin films 689–692
    - homoepitaxy of silicon on Si(100) 689
    - illumination conditions 678
    - inelastic scattering 676–677
    - instrumentation 677–684
      - LaB<sub>6</sub> emitter 701
      - laterally averaging techniques 684
      - magnetic lenses 677
      - objective lens 679–682
      - order–disorder transitions 685–687
      - Pb forms, heteroepitaxy process of 689, 690f
      - phase shift 675
      - phase transitions on Si surfaces 684
      - primary electron energy distribution 678
      - real-time and high-temperature capabilities of 684
        - real-time studies and 673
      - reflection coefficient  $R(E)$ , 674–675
      - reflectivities 674, 676
      - scattering 675
      - secondary electron energy distribution 678
      - segregation of boron 687
      - segregation of carbon 687
      - step contrast 675, 676f
      - surface topography, study of 684
      - theoretical foundations 673–677
      - thermal diffuse scattering 676
      - topographic contrast 676
      - two-dimensional compounds, formation of 687–688
      - ultrahigh vacuum (UHV) technology 677
      - vs REM 693
      - vs SEM 693
  - low-energy X-ray fluorescence (LEXRF) 757
  - lower-dimensional space, projections on 253
  - low-*k* etch process 1168
  - low light TV (LLTV) video system 379
  - lung cells, AFM cell studies of 565

**m**

  - macroscopic conductivity 561
  - Madin-Darby canine kidney cells, AFM cell studies of 565
  - magnetic field, evaluation using holography 173–180
    - deflection angle of “classical” trajectories 175
    - effects of stray field 176–180
    - of electron-transparent magnetic films 173
    - in-plane field components 175
    - iso-phasal lines 175
    - Lorentz force and 173–174
    - magnetic phase shift 173–174

- phase wedge 174
- relation with electron phase 174
- WKB approximation 174
- magnetic force microscopy (MFM) 513, 549, 1047–1049
- magnetic fringing fields 221
- magnetic moment
  - of a nanostructure 244–246
  - of single atoms 186–187
- magnetic phase shift 173–174, 175f
  - by Bohr Magneton 186–187
  - of a sphere 178f
  - vs electric phase shift 176–180
- magnetoresistance materials 561
- magnifications 616
  - TEM 12f
- Markov random field (MRF) framework 863
- martensitic transformation 1073–1077
- mass-to-charge-state ratio 802
- Materials Research Society 473
- materials science 281
- Mathematica® 156
- $R \times R$  matrix 286
- matrix effect, of SIMS 718
- Mauttach-Herzog analyzer 724
- maximum likelihood estimator (MLE) 288–290
  - for concentrations of B and N edges 296
  - for Poisson-distributed observations 289
  - properties 289–290
- maximum likelihood (ML) estimators 285
  - in MRI 833
- maximum number of electrons in the pulse 315
- MAXYMUS microscope 756
- M<sub>2</sub>C carbides 824
- MCs<sup>+</sup> technique 724
- MDMO-PPV-PCBM system 1251
- MDMO-PPV-PCNEPV blend sample 1256
- mean squared error (MSE) 286
- mechanical polishing 476
- mechanical thinning 480
  - by tripod polishing 485
- mechanical wet polishing 484
- medium-angle annular dark-field (MAADF) images 268
- medium-range order (MRO) 405–406, 424
- medium-resolution electron holography 235
- medium-resolution HAADF STEM images 262
- Meissner effect 228
- MEMS-based heaters 350–353
  - electrical connections 350
  - high-resolution imaging 351
  - Si part of heater chip 351
  - vs conventional heating holders 350
- MEMS-based nanoreactor 353–354
- 3-mercapto-1-propanesulfonic acid sodium salt (MPS) 357
- metal-carbon surface film 474
- metal/ceria catalysts 889
- metal-coated probe 512
- metal-insulator systems 562
- metallic nanobeams, strain effects 1085–1088
- metal nanoparticles, bulk diffusion of 385
- metal-organic chemical vapor deposition (MOCVD) 1221, 1228
- metaloxide-semiconductor (MOS) system 512
- Mg-based metallic glass composite 666
- microelectronic mechanical system (MEMS) 345–346, 392, 516, 1017f, 1085
  - Pt deposition process 347
- micrometer-scale monoclinic twin domains 226–227
  - lateral motion of 227
- micropillars 1138
- microsampling, FIB system 660–661
- microwave microscopy 588–591
- micro ZP 749–750
- milling technique, FIB 655–657
- Millipede Project 522, 524f
- mineralized macromolecules, of fluoroapatite-gelatin system 172
- mirror electron microscopy (MEM) 673, 697, 705
- missing wedge” of informationI 259–261
- mixed electronic-ionic conductors, for fuel cell cathodes 581
- ML estimator 285
- modern “dual-beam” instruments 255
- modulated plane wave, real-space approach to 23
- modulation methods 573–574
- modulation transfer function 133
- modulation-transfer function (MTF) 95, 155
- modulus-squared
  - of the BFP wave. *see* diffraction pattern
  - of the image wave function 15
- Mohr–Coulomb law 1135
- Moiré reflections 889
- Möllenstedt-Düker electron biprism 228
- molybdenum trioxide 381
- monochromator 13
- Monte Carlo simulations of electron 631f
- Monte Carlo-type methods 369, 433

- Moore's law 1151
- Mo-rich alloys 823–824
- morphological studies 1251
- Movie Mode DTEM 334, 335*f*
- MPDI (poly(*m*-phenylene isophthalamide)) 1360
- multibeam dynamical simulation approach 32
- multiferroic materials 1273
- multifrequency methods, of SPM 552–554
  - band excitation (BE) approach 553–554
  - dual-AC resonance tracking (DART) method 553
  - fast lock-in sweep approach 553
  - force–volume imaging mode 554
  - oscillator and cantilever transfer functions 552
  - real-space approach 554
  - ring down approach 553
  - thermal (white noise) excitation 552–553
- multigate field effect transistors (MugFETs) 1151
- multilens microscopes 1
- multiple-frequency Ztherm 587–588
- multiple-probe SPM systems 596
- multiquantum wells (MQWs) 527
- multislice algorithm 140
- multislice methods 64, 73–74
- multiwalled carbon nanotubes (MWCNTs) 999–1001, 1003
- myocytes, AFM cell studies of 565
  
- n**
- NaCl crystals 326
- nanoarea electron diffraction (NED) 439–443
- Nanobeams project 725
- nanobelts/nanoribbons 961
- nanocrystalline-MgO (nano-MgO) practical powder catalysts 399
- nanodiamonds 1012, 1018
- nanodiffraction 197, 199*f*
- nanofabrication techniques 346
- nanolab
  - Cu electrodeposition, using TEM 357–358
  - gas nanoreactors 353–356
  - measuring electrical properties at 346–350
  - measuring optical properties 360–362
  - MEMS-based heaters 350–353
  - sample preparation for 362–370
  - sculpting with electron beam/matter interaction 365–370
  - setups for 345–346
  - TEM with liquid nanoreactors 356–360
- nanolaminates
  - far-from-equilibrium 329
  - self-propagating reactions in 325–326
- nanolithography 522
- nanomaterials, importance of 281
- nanometer-scale resolution 615
- nanometer-sized coherent electron probe 439
- nanoparticles
  - bulk structure 887–900
  - chemical bonding and oxidation state 936–939
  - chemical identification and quantification of individual 930–936
  - electron microscopy techniques 920–925
  - imaging 883–884
  - lattice distortions and interface structure 911–920
  - mobility 947–948
  - nanoanalytical characterization of 925–929
  - optical information 929–930
  - shape and surface structure 900–911
  - *in situ* electron microscopy techniques 940–949
  - size 884–887
  - synthesis of 944–947
  - under working conditions 948–949
- nanoscale deformation twins 1071–1073
- nanoscopy 3
- nanosecond timescale experiments 321–322
- NanoSIMS 50 operator 727
- nanostructures 46
- nanotoxicity 879
- nanotubes
  - carbon 971–973, 984–985, 988–990
  - *in situ* electric transport property of carbon 988–990
  - *in situ* mechanical properties 985–988
  - structure 961
- nanowires
  - bright-field TEM image 964
  - defects in 974–983
  - determination of growth directions 962–968
  - 3D structure 968
  - Si, catalyzed by Au and Pd nanoparticles 983–984
  - *in situ* mechanical properties 985–988
  - *in situ* TEM investigation of electrochemical properties 991
  - structure 961
  - surface reconstruction 969–971
  - ZnO 965–966

- National Center for Electron Microscopy (NCEM), Berkeley 1101
- National Centre for X-ray Tomography (NCXT) 751
- National Renewable Energy Laboratory (NREL) 1214
- Nb<sub>2</sub>O<sub>5</sub>-based materials 2
- NC-AFM 566
- n-dopants 170
- N-doped carbon nanotubes (CNTs) 349–350
- *I*–*V* curves 349–350
- n-doped gallium nitride films, near-field CL measurements on 531
- near-edge absorption X-ray spectromicroscopy 1056–1058
- near-edge X-ray absorption spectroscopy (NEXAFS) 756
- near-field microwave impedance microscopy 588
- near-field microwave microscopy 588
- near-field piezoelectric interaction 516
- near-field tip-enhanced Raman and confocal microscopy 1049–1050, 1051f
- near-ultraviolet PEEM 681
- negative spherical-aberration imaging (NCSI) 82
- ACTF for 90
- of ferroelectric polarization 102
- of graphene 102
- for higher sample thicknesses 91–94
- of interface between SrTiO<sub>3</sub> and LaAlO<sub>3</sub> 102
- measurements of the atomic shifts 103, 104f
- of Pb(Zr<sub>0.2</sub>Ti<sub>0.8</sub>)O<sub>3</sub> 103f
- practical examples of 102–104
- of PZT/SrTiO<sub>3</sub> interface 102
- strontium titanate (SrTiO<sub>3</sub>) 87–88
- in YBa<sub>2</sub>Cu<sub>3</sub>O<sub>7</sub> 102
- neodymium-doped YAG lasers 321
- Ni AF1410 alloy 824
- NiAl B2 phase 330–331
- Ni-based superalloy 267, 267f, 1089
- Ni-depletion zone 1083
- NiFe toroidal magnets 228
- Nion UltraSTEM 113, 1183, 1183f–1184f, 1191f
- Ni-rich system 330–331
- observations of morphological transients in 331–333
- Ni-silicide phases 1164
- Ni-Ti austenite matrix 1090
- Ni<sub>4</sub>Ti<sub>3</sub> precipitates in Ni-Ti shape, atomic structure of 1077–1081
- deformation and concentration gradients 1081–1083, 1084f
- elastic constant measurements 1084–1085
- nitrogen-doped graphene 86
- Ni-YSZ solid-oxide fuel cell 666, 667f
- N-K edge EELS spectra 1220, 1219f–1220f
- N-methyl-pyrrolidone (NMP) 1039
- NMR imaging 254
- noise estimation methods
- from a background region 845–848
- from complex data 844–846
- double acquisition methods 844, 849–850
- from magnitude data 846–850
- from a nonbackground region 848–849
- region of constant amplitude and phase 844–845
- single acquisition methods 844
- NoiseFigure, of a holographic system 164–165
- noncentrosymmetry 196
- noncontact (NC) profilometer 542
- noncrystallographic phase problem 443–445
- noncrystallographic phase problem, ITAs for 439
- non-ion-beam-related techniques 730
- nonlinear optical (NLO) activity 1370
- nonround optical elements 14
- nonsystematic errors 284, 293
- normal absorption length 22
- normalization condition 425
- normalized probability distribution 425
- normalized variance 426–427
- of continuous random network (CRN) 430
- of paracrystalline Si grains 430
- for random distribution 431
- of a set of atoms 428
- normal wave vector component 25
- N*–*R* degrees of freedom 291
- n*th-order corrector 122
- nuclear energy loss 652
- null hypothesis 291
- numerical aperture (NA), of ZP 755
- numerical multibeam approach, to diffraction 30–35
- aperture movement corresponding to diffraction patterns 32
- BF and DF intensity distributions 31
- Bragg condition 31
- dark field images 31
- excitation errors 32
- image simulations for SR case 31
- reciprocal lattice points 30, 32
- using Bloch wave simulation 31–32
- zone axis case vs SR case 30

- numerical wave-optical image processing 156
- nylon, plasmon excitation energies of 271
- o**
- Oak Ridge National Lab (ORNL) 855
- object domain error metric 468
- object entrance plane, degree of coherence of illumination in 164
- object exit wave 160
  - of reconstructed wave 160
- object function reconstruction, from diffraction pattern 466
- objective function 856
- objective lens 13, 14f
  - aberrations 15–16
- objective lens, of STEM 115
- objective-lens spherical aberration parameter 82
- observation, TEM 12f, 18
- octahedral tilts 143
- o-dichlorobenzene 359
- off-axis electron holography 290, 444
  - amplitude and phase shift of the specimen 231–232, 231f
  - applications 239–244
  - basis and governing equations 228–232
  - beam illumination 233
  - coherent image formation 229
  - degree of smoothing of final phase images 237
  - electron beam direction 236
  - electron biprism in 229, 233
  - electron-optical configuration 228–229, 229f
  - electron wavefunction in the image plane 229–230
  - electrostatic contribution to phase shift 235
  - experimental requirements 233–235
  - fabrication onto Si<sub>3</sub>N<sub>4</sub> windows 244
  - of ferromagnetic domain walls 228
  - Fourier transforms 231–232
  - fringe contrast 233
  - fringe spacings 234
  - high-angle annular dark-field images of 238
  - history of 227–228
  - inner potential contribution to phase shift 237–238
  - interference fringe contrast 229, 230f
  - interference fringe visibility 233–234
  - lateral movement and rotation of biprism 233
    - magnetic contribution to phase shift 236–237, 239f
    - in magnetic-field-free conditions 239, 242
    - magnetic induction 236, 240f–241f
    - magnetization direction 237–238
    - modes 235
    - modulation transfer function 235
    - in OOP magnetic fields 242–243
    - overlap width 233, 234f
    - phase resolution 234
    - phase shift 235–239
    - in polycrystalline Ni<sub>79</sub>Fe<sub>21</sub> 243
    - reference image intensity 230–231
    - signal-to-noise ratio 234
    - specimen image intensity 230–231
    - switching variability and 243
    - in vortex-type magnetic domain 244
- off-axis holography 66
- off-axis image-plane holography 197
- off-diagonal matrix 23
- oleylamine 359
- oligo(*p*-benzamide)s (OPBAs) molecules 1357
- OL resolution function 440
- optical aberrations 83
- optical-beam-induced current (OBIC) examinations 515
- optical interferometry on Earth 420
- optical lever, of SPM 546
- optical microscope 1
- optical microscopy 1339–1342
- optical profilometers 728
- optical properties, investigation using TEM 360–362
- optical transfer function 133
- optimal experimental design, of HRTEM experiments 300–303
  - amorphous structures 302
  - for correcting spherical aberration and chromatic aberration 303
  - Poisson-distributed observations 301–302
- optimal solution 856
- optimization, of reconstructed wave 162
- optimization problem 856
- optimum defocus value 59
- optimum resolution 119
- order sorting aperture (OSA) 752
- Orion constellation 420
- oscillating cantilever AFM techniques 541
- oscillating cantilever tip system 514
- out-of-plane (OOP) component, of magnetic field 225
- oxide superlattices, colossal ionic conductivity in 1193–1198

- oxygen electrolytes 581  
oxygen lattice distortions, imaging of 1183–1189  
oxygen stoichiometry 388  
oxygen–titanium atom separation 88
- p**
- parallel electron energy loss spectroscopy (PEELS) 378f  
parallel illumination, TEM 17, 18f  
parameter estimation method  
– accuracy 282  
– for calculating interatomic distances 295  
– confidence regions and intervals 292  
– distributional assumptions 291  
– effects of modeling errors in reconstruction 295  
– for electron microscopy applications 292–303  
– expectation values  $E(w_n)$  283–284  
– good starting values for parameters 290  
– maximum likelihood estimator (MLE) 288–290  
– mean squared error (MSE) 286  
– model of observations 283–285  
– nonsystematic errors of observations 284  
– normality assumptions 291  
–  $N \times 1$  vector of observations 283  
– parameterized function 284  
– precision 282, 286–288  
– properties of estimators 285–286  
– resolution vs precision 293–294  
– role of amorphous layers 295  
–  $R \times R$  vector of observations 286  
– standard deviation 286  
– for statistically independent Poisson-distributed observations 283–284  
– stochastic variable 283  
– unbiased estimators 286  
– variance 286  
parametric two-component mathematical model 293  
particle–wave duality, of electrons 1  
Pauli exclusion principle 315–316  
Pauli principle 504, 507  
PbSe–Au supercrystal 899  
 $Pb_{1-x}Sn_xTe$  1274  
p-dopants 170  
p-doped GaN layer 531  
Pd particles, hydrogenated 355  
Pd thin film 1086–1088  
PEELS/GIF (parallel electron energy loss spectroscopic/Gatan image filtering) functionalities 379  
perfect crystal theory 21–25  
– Bloch wave approach 24–25  
– Fourier space approach 21–23  
– real-space approach 23–24  
perovskite materials  
– fine structures of 1189–1193  
– imaging of oxygen lattice distortions in 1183–1189  
perturbed reference wave 166  
perylene-tetracarboxylic dianhydride (PTCDA) 1369  
phase contrast, of aberration-corrected instrument 85–86  
phase contrast, of STEM 128  
phase contrast image  
– in high-angle scattering 134  
phase contrast imaging 113  
phase contrast magnetic resonance (PCMR) images 835–836  
phase contrast microscopy 58–59  
phase-contrast transfer function (PCTF) 85  
phase detection limit 164  
phase grating approximation 457  
phase grating equation 24  
phase image, of reconstructed wave 160–161  
phase-locked loops (PLL) 550  
– based frequency-tracking methods 551–552, 554  
phase object approximation (POA) 409  
phase object function 77  
phase problem in crystallography 443–445  
phase problem in diffraction 438  
phase retrieval algorithm 451–454  
– charge flipping (CF) algorithm 454  
– difference map (DM) algorithm 454  
– error reduction (ER) algorithm 452–453  
– generic iterative 452f  
– Gerchberg–Saxton (GS algorithm) 452  
– hybrid-input-output (HIO) algorithm 453  
– phasing experimental diffraction 461  
– simulation studies 455–461  
phase retrieval methods 417  
 $\pi/2$  phase shift 85, 91  
phase shift, calculation of 73  
phase shift, of atoms 182f  
– by a Bohr Magnetron 189f  
– of PTO ( $PbTiO_3$ ) 191f  
– by single charges 189f  
phase transfer function 58  
phase wrapping 161  
(6,6)-phenyl-C61-butyric acid (PCBM) 772

- Philips CM30 microscope 1232
- Philips CM30T TEM/STEM 377
- phonon dispersion model 140
- phonon waves 410
- photoemission electron microscopy (PEEM) 673, 751–752
- photomultiplier tube (PMT) 625
- photon emission microscopy 510
- photon-in, photon-out character of STXM 756
- photon-induced near-field electron microscopy (PINEM) 1039
- photon tunneling 503*f*, 504
- photovoltaic (PV) technology 1211
  - experimental 1213
  - fundamental and practical losses associated with process 1212
  - p–n junction-based 1211
- P3HT–PCBM, ET investigation 1263–1265
- picometer precision electron microscopy 95–96
- picosecond-scale single-shot coherent electron imaging 316
- piezo-driven needle 346
- piezoelectric actuators 505–506
- piezoelectric compounds 580
- piezoresistive cantilevers 523
- piezoresponse force microscopy (PFM) 539, 579–583
  - high-sensitivity 580
  - local hysteresis loops 581
  - operation 580
- piezoresponse force spectroscopy (PFS) 579
- piezoresponse microscopy 516, 517*f*
- Planck constant 73
- Planck's constant 83, 223, 418
- plane wave 19
- plane-wave illumination 408
- $\lambda/4$  plate 85
- platelets, AFM cell studies of 565
- pMOS transistor 492
- pMOS transistors 485, 487*f*
- p–n junction-based PV technology 1211
- p–n junction-based solar cells 1212
- p–n junctions 268
  - 3D potential distribution 268, 269*f*
  - reconstruction of 269
- point analysis mode 925
- point spread, for atomic resolution imaging 83–84
- point-spread function 51
- point-spread function (PSF) 51
  - of CCD camera 184
  - holographic methods 66
  - in incoherent imaging 58
  - in real imaging 51, 53
  - for recovering the object exit wave 160
- Poisson's equation 19
- Poisson-distributed image pixel values 293
- Poisson-distributed observations
  - Cramér–Rao lower bound (CRLB) for 287–288, 301
  - likelihood function for 289
  - likelihood ratio test for 291–292
- Poisson's ratio 39
- Poisson-type speckle 415
- polarization switching 581
- polarized electron source 319
- poles 807
- polyaniline (PANI) 1360
- polybutadiene 168
- polycrystalline chemical vapor deposition (CVD) 529
- polycrystalline Co nanoparticles 242
- polycrystalline SiC matrix 490
- poly(9,9-dioctylfluorene-co-benzothiadiazole) (F8BT) 771
- polyelectrolytes 582
- polymer blend film for solar cells, electrostatic force microscopy of a 513, 514*f*
- polymer chain packing 1358–1360
- polymer/fullerene solar cells 1266
  - ZnO domain 1266–1267
- polymer microstructure analysis, by soft X-ray microscopy 771–773
- polymers 1337
- polymer solar cells (PSCs)
  - electron tomography 1259–1263
  - morphology requirements of photoactive layers in 1249–1250
- polymer STXM 752
- poly[2-methoxy-5-(3*c*,7*c*-dimethyloctyloxy)-1,4-phenylene vinylene] (MDMO-PPV) 772
- poly(methylmethacrylate) (PMMA) 725
- polymorphism 1337
- polymorphs 1337–1338
- polystyrene 167–168
- polystyrene (PS) 725
- positioning system, of SPM 543–545
- position-sensitive photodetector 546
- positive phase contrast 85, 90–91
- positive semidefinite matrix 287
- positive value of spherical aberration coefficient (PCSI) 98
- positron emission tomography (PET) 254
- posteriori aberration correction 153
- posteriori aberration correction, of reconstructed wave 162



- potential energy landscape (PEL) 1145  
Potts' interaction penalty 872  
Poynting vector 83  
preferential thinning 481  
primary structure 1338  
principal component analysis (PCA) 141, 598, 1184  
principal low-index crystal direction 96  
printable solar cells (PSC) 1248–1249  
probability density functions (PDFs), in MRI  
– Gaussian 833–834  
– generalized Rician 835–836  
– of phase data 836–837  
– Rician 834–835  
probe-forming lens 115  
probe-forming lens, of STEM 115  
probe intensity distribution, of STEM 119  
– expression for increase in probe size with probe current 120, 121f  
– full width half maximum (FWHM) of 120  
– HAADF scattering and 135  
– for La, MnO, and O columns in LaMnO<sub>3</sub> 135, 136f–137f  
profilometer 541  
projected density of states (PDOS) 1224–1225  
projection slice theorem 256  
propagator equation 24  
Pt atoms 111–112  
Pt deposition process 347  
– with electromigration processes 347, 348f  
Pt heater 353  
Pt nanobridges 346–347, 370  
Pt nanocrystals 360  
Pt nanoparticles 265, 383  
Pt–Pd nanoparticles 397, 398f  
ptychography, electron 438  
p-type CIS chalcopyrite-n-type ODC heterojunction model 1235  
p-type Czochralski-grown (CZ) c-Si wafers 1214  
pulse compression, of DTEM 339  
pulsed RF guns 339  
pump-probe experiments 311, 322  
pump-probe voltage signals 562  
punching 475  
pure intensity imaging 153  
pyrochlore (*Fd3m*)-related structure 895
- q**  
Q-factor 551  
Q-switched laser systems 333  
quadrupoles 14
- quantitative chemical concentration measurements 296  
quantitative electron tomography 273–274  
quantitative HREM 65–72  
– electron channeling 67–70  
– exit wave reconstruction 67  
– model-based fitting 65  
– phase retrieval 65–67  
– refining of images 70–72  
quantitative HRTEM 284  
quantitative thermal conductivity analysis 521  
quantum-mechanical principles 73  
quantum mechanics 1, 407  
quantum size effects (QSEs) 698  
quartz-resonator-based force sensors, with STM tips 560  
quartz tuning fork 510  
quasiparticle electron spectroscopy 554
- r**  
radial distribution functions 429  
Radon, Johan 253  
Radon space 255  
Radon transform 253, 255  
random-axis anisotropy 227  
Rayleigh, Lord 133  
Rayleigh criterion 135, 184, 501  
Rayleigh-distributed background region, in MR images 848  
Rayleigh PDF 835  
Rayleigh resolution limit 293–294  
R5 cells, AFM cell studies of 565  
R-dimensional parameter space 290  
reactive ion beam etching (RIBE) 483  
reactive multilayer foil (RMLF) 325  
reactive nanolaminate films 324–326  
reactor-type gas-manifold system 378  
real imaging, of a real object 51–53  
– blurring 51  
– deblurring 53  
– final image 51  
– Fourier transforms 52  
– impulse response function 53  
– noise 52  
– shape of the PSF 51, 53  
– spatial frequency component 52  
– transfer function 52–53  
real-space approach 554  
real-space approach, to imaging 23–24  
real-space formalism 19  
real space reconstruction, using backprojection 256–259  
real-time autotuning 145

- real-time dynamic *in situ* AC-TEM studies
    - 400*f*
  - real-time imaging of magnetization reversal processes 224
  - reciprocal lattice points, of TEM 17
    - in numerical multibeam approaches 30, 32
  - reciprocal lattice vector 20
  - reciprocal lattice wave vectors 409
  - reciprocal space 1336
  - reciprocity principle, between STEM and TEM 125–129
  - reconstruction, of p–n junctions 269
  - reconstruction accuracy 801
  - reconstruction techniques 271–272
  - redox-active molecules 582
  - refining of images 70–72
  - reflection coefficient  $R(E)$ , 674
  - reflection electron microscopy (REM) 693
  - reflectron-type TOF mass spectrometer 721
  - relative sensitivity factor (RSF), of SIMS 716–717
    - of  $\text{Na}^+$  ions in Si 717
  - relativistic electron mass 21
  - relativistic electron wavelength 223
  - relativity theory 1
  - replica techniques 474
  - resistive anode encoder (RAE) 654
  - resolution, of an optical microscope 1
  - resolution criteria, of electron microscopy 293–294
  - Resolution Enhancement with Nanoparticle Random Tracking (RENaRT) 1342
  - resolution limit, for incoherent HAADF-TEM imaging 317, 319
  - resolution of the instrument, definition 52
  - resolution principle, for atomic resolution imaging 83–84
  - resolved pixel 164
  - resonance tuning technique 663
  - R factor 48, 468, 550
  - R-factor 65
  - Rh(1%)/ $\text{Ce}_{0.8}\text{Pr}_{0.2}\text{O}_{2-x}$  catalyst 389, 391*f*
  - Rh nanoparticle 889
  - rhodium/ceria catalyst 889
  - rhombohedral phase (R-3m) 1275
  - Rician-distributed magnitude MR data 846
  - Rician PDF 834–835
    - moments of 835
    - to Rayleigh distribution 834
  - Rohrer, H. 505
  - Ronchigram 123–125, 125*f*
    - for amorphous and crystalline specimens 125
    - angular deviations and 124
    - for coherent probe 124
    - crystalline 125
    - in a diffraction plane 123
    - at larger angles 124
    - method for obtaining 123
    - for nonzero aberrations 124
    - patterns at different angles 123
    - recorded at 300 kV on HB603U 126*f*
    - as a transmitted shadow of the sample 123–124
  - root mean square errors (RMSE) 295, 296*t*
  - Rose-corrector 81
  - Rose criterion 317
  - R-phase 1081, 1083
  - Ru/ $\text{CeO}_2$ - $\text{ZrO}_2$  catalyst 896
  - Ruska, Ernst 2
  - Rutherford backscattered ions (RBI) 629
    - of a copper grid contaminated with carbon 630*f*
    - $\text{He}^+$  ions 629*f*
  - r-values 425
- s**
- samarium-doped ceria 581
  - sample preparation techniques, for TEM 1346–1351
    - beam-induced heating 483
    - biological crystalline materials 483
    - chemically assisted ion beam etching (CAIBE) 483
    - cross-section TEM samples of multilayer structures 481
    - Cu–Cr/Mo–C 479
    - detrimental effect of ion beam sputtering 482
    - direct methods 475–493, 1346–1348
    - electron-transparent specimens 478
    - freeze fracture and etching 1350–1351
    - heterostructure systems 479
    - indirect methods 474
    - liquid nitrogen ( $\text{LN}_2$ ) cooling 483
    - mechanical thinning 480
    - mechanical wet polishing 484
    - polycrystalline Cu specimen 479, 479*f*
    - preferential thinning 481
    - radiation-induced defect agglomeration or segregation 483
    - reactive ion beam etching (RIBE) 483
    - reactive ion techniques 483
    - single- or double-sector thinning 480
    - Si/SiGe heterostructure 481–483, 481*f*, 484*f*
    - site-specific lift-out 1155
    - staining 1349–1350

- thin slice of material by chemical dissolution 478
- vitrification 1348–1349
- Yb/Si specimen preparation 478
- Sanyo's heterojunction with intrinsic thin layer (HIT) solar cells 1213
- sawing 475
- Sb-promoted tin oxide nanocatalysts 385
- scalar valued parameter 287
- scaling laws 1143–1144
- scanning capacitance microscopy (SCM) 512, 586–587
- scanning electron microscopy (SEM) 3, 615–616, 855
  - aberration correctors 622
  - backscattered electrons and ions 628–634
  - basic components of microscope 617f
  - beam damages 640–642
  - beam rate scans 619
  - brightness 619, 619f
  - charging and charge control 636–640
  - with cold field emitter gun (CFEG) 620
  - contrast transfer function (CTF) 623, 624f
  - damage-free imaging 666
  - depth of field 622
  - digital 618
  - dual-beam system 666
  - dynode electrodes 654
  - electron backscatter diffraction patterns 634–635
  - electron beam–induced conductivity (EBIC) 635–636
  - escape depth region for electron 623
  - FIB-SEM dual-beam system 664–666, 665f
  - for fluorescent X-rays 618
  - Fourier transform of complete image 623
  - general characteristics of electron beam–generated SE signals 626
  - He<sup>+</sup> ions (HIM) beam 615, 620–621
  - image artifacts 636–642
  - instrumentation 617–619
  - ion-generated secondary electron (iSE) signal 621
  - irradiation from 623
  - lower-cost 618
  - microprobe mode 654
  - modes of operation 623–642
  - optimally adjustments 623
  - performance of microscope 619–623
  - primary signals used 652
  - quantitative comparison with FIB 653t
  - resolution conditions 620–621
  - secondary electron imaging 623–628
  - SEM/HIM images 625, 633
  - SE1 spectrum 624–625
  - SE2 spectrum 624–625
  - SE3 spectrum 626
  - signal-to-noise-ratio (SNR) 619
  - “snorkel” lens 618
  - scanning electron microscopy with polarization analysis (SEMPA) 704
    - advantages 705
  - scanning gate microscopy (SGM) 577
  - scanning impedance microscopy 574–576
  - scanning impedance microscopy (SIM) 577, 579
  - scanning Joule expansion microscopy (SJEM) 518, 519f
  - scanning low-energy electron microscopy (SLEEM) 693
  - scanning near-field acoustic microscope (SNAM) 516
  - scanning near-field optical microscopy (SNOM) 3, 505–510
    - advantages 509
    - constant force measurement 506
    - integrated circuits (ICs), optical inspection of 509
    - operation modes 507
    - optical inspections of ICs 509–510
    - resolutions 505–506
    - SNOM/SEM hybrid system 531
    - surface roughness and sliding friction 506–507
  - scanning near-field thermal microscopy (SThM) 518
  - scanning photocurrent microscopy (SPCM) 997, 1042–1044
  - scanning photoelectron microscopy (SPEM) 746, 1059
  - scanning probe microscopy (SPM)
    - AC current measurements 584–586
    - advanced SFM/SEM microscopy 522–533
    - AFM data acquisition 548
    - amplifiers 546
    - based impedance measurements 545
    - cantilever detection 545–546
    - classical detection strategies in 550–551
    - combining local electrical and mechanical excitation 598–599
    - data processing and acquisition 550–554
    - DC current measurements 583–584
    - detecting an evanescent wave or an evanescent field 503–505
    - detection of electric/electronic sample properties 510–516

- scanning probe microscopy (SPM) (*contd.*)
  - detection of electromechanical and thermoelastic quantities 516–522
  - detector system 545–547
  - 1D spectra 598
  - dynamic detection 596–597
  - electric and magnetic field distributions 501
  - electrochemical 545
  - electronic and mechanical feedback systems 548
  - feedback circuit 541–542
  - force-based 546
  - Fresnel diffraction and reciprocal principles 503
  - high-resolution spectroscopic imaging 543
  - image acquisition rates 548
  - limitations 547
  - lock-in amplifiers (LIAs) 551
  - manipulation of matter by 593–594
  - mass spectrometric imaging in 592
  - multidimensional data analysis and interpretation 597–598
  - multifrequency methods 552–554
  - multiple-probe 596
  - near- and far-field investigations of a static electric dipole 499–501, 500*f*
  - noise level 546
  - novel multifunctional probes 551*f*
  - operating principles of 540
  - optical lever 546
  - oscillating cantilever AFM techniques 541
  - permalloy probe 542
  - piezo-tube scanner for 545*f*
  - platforms 595–596
  - PLL-based frequency-tracking methods 551–552
  - positioning system 543–545
  - principles 540*f*
  - probe functionality 547–550
  - probes and imaging modes 595*f*
  - profilometer 541
  - of Pt–Ir alloy wire 548
  - Rayleigh criterion 501
  - science of localized probes 541–554
  - SEM images of 547, 547*f*
  - spatial resolution 501, 546–547
  - surface topographic mapping techniques 541–542
  - temperature-controlled environment 543
  - theory of diffraction of an aperture 502
  - thermal method 587–588
  - timeline of progress 544*f*
  - tip–probe distance 542
    - tip–sample distance 542–543, 545
    - tools 540
    - vertical motion of probe 541
    - voltage modulation 574–583
- scanning spreading resistance microscopy (SSRM) 511, 545
- scanning transmission electron microscopy
  - high angle annular dark field (STEM-HAADF) 1003
- scanning transmission electron microscopy (STEM) 2, 355, 379, 420, 437
  - aberration-corrected images 140
  - aberration correction in 109–111
  - aberrations of the system 117
    - ADF 4, 131
  - adjacent heavy atom columns in 112
  - advantages 115
  - amplitude distribution of probe 118
  - annular dark-field (ADF) imaging 109
  - aperture of probes 116
  - basic components of 113–116
  - coherent and incoherent imaging 129–133
  - collector aperture in 128
  - components 117*f*
  - condenser lenses 115
  - contrast creation in carbon-based BHJ photoactive layers 1253–1254
  - contributions to probe broadening 121–122
  - crystal morphologies using 263
  - defocus of 119–120
  - demagnifications 115
  - depth sectioning 135–140
  - design and optimization of objective lens 115
  - DPC images 224
  - effect of beam divergence 127
  - elastic scattering mechanisms and 125
  - energy spread through a damping factor 127–128
  - field emission gun 111
  - flexibility of 115
  - focus values  $\Delta f$ , 121
  - future outlook 144–145
  - geometric aberrations 117
  - geometric optimum probe 120
  - gun brightness 121
  - HAADF detector 115
  - HAADF image 141, 141*f*
  - high-angle annular dark-field (STEM HAADF) images 254, 262
  - image contrast and 437–438
  - image stimulation and quantification 140–144

- imaging in 116–144
- imaging of individual Pd atoms 128–129
- inelastic scattering mechanisms and 126
- layering of Au particles on TiO<sub>2</sub> layer 355–356
- medium-angle annular dark-field MAADF images 268
- of monolayer BN 113
- objective (probe-forming) aperture 118
- optimum aperture 119–120
- phase contrast images 128
- probe formation 116–123
- probe-forming aperture size 122
- probe-forming lens of 115
- probe intensity distribution 119–120
- reciprocity between TEM and 125–129
- and reconstruction of metal oxide catalysts using Au nanoparticles 263, 263f–264f
- resolution of lens 115
- Ronchigram 123–125
- *in situ* measurement 115
- small pole piece gaps 111
- spatial frequencies 121–122
- spherical aberrations 117
- of tilted surfaces 263
- tomography 263
- scanning transmission X-ray microscopy (STXM) 746, 752–757
- scanning tunneling hydrogen microscopy 549
- scanning tunneling microscopy (STM) 3, 503–505, 554–563, 558f, 1039–1042
  - atomically resolved 559
  - data acquisition and control methods 555f–556f
  - imaging of PTCDA/Ag(111) 561f
  - principle of 505f
  - pseudogap states 561
  - “quantum corral” image of an electron standing wave 557
  - quartz-resonator-based force sensors 560
  - semiconducting surfaces 561
  - “soft” modification of tunneling junction 560
  - spectroscopic modes 557
  - STS spectrum 561
  - time and space resolutions 562–563
  - tip effects 559–560
  - tip–surface junction conductance 557
  - topographical imaging of Au 554
  - topographic imaging modes 557
  - tunneling into low conducting surfaces 562
- scanning tunneling spectroscopy (STS) 1039, 1042
- scanning X-ray transmission microscopy 354
- scanning yield techniques 757–763
- scattered electron wave 443
- scattered spherical wave amplitude 408
- scattering matrix 23
- scattering phase 181
- Scherzer defocus 59
- Scherzer resolution 82
- Scherzer’s phase-contrast theory 82
- Schottky contact displacement 529
- Schottky contact high-resolution 528
- Schottky designs, normalized brightness for 120
- Schottky emission electron gun 13
- Schottky field-enhanced thermionic emitter 617
- Schrödinger equation 21, 35, 74, 95, 140
  - stationary 75
  - time-dependent 75–76
- scientific revolutions 539
- scintillator-photomultiplier tube (PMT) detector 653–654
- scratch-free final polish 477
- sculpting with electron beam/matter interaction 365–370
  - for Cu<sub>x</sub>Bi<sub>2</sub>Se<sub>3</sub> 369
  - for detecting biopolymers 366–367
  - in experiments of nanopore formation 366
  - in a focused ion beam (FIB) 365–366
  - Ga ions 367–369
  - helium ion beam 369–370
- secondary electron emission microscopy (SEEM) 677
- secondary electron imaging 623–628
  - of gold on carbon 627f
  - “high noon” shadow-free view 628
  - iSE1 and iSE2 components of helium source 625
  - SE1 spectrum 624–625
  - SE2 spectrum 624–625
  - SE3 spectrum 626
- secondary electron (SE) detector 615
- secondary ion mass spectrometer (SIMS) 170, 654
- secondary ion mass spectroscopy (SIMS)
  - artifacts 717–719
  - biological 731–734
  - cellular layer imaging 728
  - cluster- and polyatomic primary ion sources 713
  - depth resolution 714
  - dynamic 711

- secondary ion mass spectroscopy (SIMS)
  - (*cont'd.*)
  - fundamentals 709
  - imaging and data analysis 727–731
  - instrumentation 719–727
  - ionization efficiency 712–713
  - lateral resolution 713–714
  - mass resolution 714–716
  - matrix effect 712, 718
  - near-surface analysis 711
  - physical principles 709–712
  - quantification of sample composition 716–717
  - relative sensitivity factor (RSF) 716–717
  - sample charging 719
  - sample preparation of biological materials for 734–739
  - sensitivity 715
  - sensitivity of 726
  - sputtering process 709–712
  - sputter yield 712–713
  - “static limit” for 710–711
  - steady states 716
  - surface topography 718–719
  - technical details 712–719
  - ToF-SIMS instrument 716, 719–721
  - transmission 715–716
- secondary spherical wave, Huyghens source for 74
- Seidel aberrations 15
- selected area aperture 13
- selected area diffraction (SAD) aperture 327
- selected-area electron diffraction (SAED) 441
  - area of diffraction in 441
  - mode of hydrogen loading of palladium 355*f*
- selective etching, of unimplanted regions 663
- self-propagating reactions 324–326, 333
  - in Al/Ni nanolaminate films 326
  - exothermic 326
  - of nanolaminates 325–326
- semiconductors, optical properties of 46
- SEM/LC-SEM
  - coordinate systems of scanner 857–860
  - geometric calibration of 857–860
  - imaging sensor 857
  - stereo image acquisition procedure 858–860
- sensitivity, of SIMS 715
- sequential microtomy 730
- sextupoles 14
- SFM/SEM-based hybrid systems 523–533
  - deflection detection method 524
  - directional thermal conductivity analysis 526
  - laser deflection method 527
  - multiquantum wells (MQWs) 527
  - nano-Newton precision 525
  - near-field acoustic microscopy 527*f*
  - piezoresistive cantilevers 523
  - probes 525
  - probe–specimen interaction mechanisms 526
  - thermal characterization of ICs 526
  - thermal–mechanical interactions 528
- Shannon informational entropy 433
- shaving technique 522
- shear displacement jump (SDJ) 1132
- Shockley partial dislocations (SPDs) 1072
  - passage 1071–1073
- Shockley partials 1072
- Shockley–Queisser limit 1212
- Shockley-Reed-Hall (SRH) recombination 1212
- short-range order 424–425, 429
- shot noise speckles 407
- Si adatom 562
- Si atom 412–413
- Si-based device technology 1156
- Si cantilevers 546
- Siemens 2
- signal amplitude estimation, from MR data
  - for background region 846–847
  - from complex data 838–840
  - from continuous magnitude MR data 847
  - from discrete magnitude MR data 847–848
  - from magnitude data 840–842
  - raw MR data 837–838
- signal/noise properties, of reconstructed wave 163–165
- significance level 292, 297
- Si implantation 663
- Si lattice 1180
- Si-L edge 1219–1220, 1219*f*–1220*f*
- silicon-based semiconductor devices, nanoscopic applications
  - bonding and packaging 1170–1171
  - debugging 1171–1172
  - doping methods 1161–1163
  - epitaxial growth 1156–1158
  - fault localization methods 1171–1172
  - gate structures 1163–1164
  - metalization 1165–1168
  - methods 1157*t*–1158*t*
  - metrology 1156
  - new device concepts 1172

- silicides 1164
- strain measurements 1158–1160, 1160*t*, 1161*f*
- structural characterization methods 1171
- three-dimensional structures 1168–1170
- silicon-based technology 356
- silicon-on-insulator (SOI) FinFETs 1151
- silicon wafer, electron-channeling pattern from 631
- SI mode 925
- simple harmonic oscillator (SHO) 552
- simplified channeling theory 284
- simulation studies, CDI 455–461
  - Argand plots for exit wave function 458, 459*f*
  - complex object reconstruction 458, 460
  - construction of Au nanoclusters 456–458
  - degree of damping 461
  - dynamical diffraction patterns 456–457, 460
  - dynamical scattering 460
  - dynamical scattering effects 456
  - kinematical diffraction patterns 456–457
  - multiple scattering on image reconstruction, effect of 457
  - numerical experiments 456
  - oversampling 460
  - *R* factors 457
- simultaneous iterative reconstruction technique (SIRT) 258
- Si nanowire 139–140
- Si-needle, pn-junctions in 170
- single-frequency scanning thermal expansion microscopy (SThEM) 587–588
- single-shot extreme ultraviolet laser imaging, 1056
- single-particle cryo-EM 5
- single-particle cryo expectation maximization (EM) 50
- single-pulse diffraction studies, of reactive foils 327–329
- single-shot nanosecond TEM imaging 311
  - picosecond-scale of 316
  - theory of resolution limits for 315
  - time resolution trade-offs 316–320
- single-shot pulsed imaging 315
- single-walled carbon nanotube (SWCNT) 999–1001
  - determination of chiral angle 1020–1021
  - pristine 1020
- singular value decomposition (SVD) 765–766
- sinogram 255
- Si p–n device 268
- SIRT algorithm 258*f*
- Si/SiGe heterostructure, preparation of 481–483, 481*f*, 484*f*
- site-specific lift-out sample preparation 1155
- site-specific single-atom spectroscopy 1027
- Si (001) wafer, cleavage technique for 477
- Si<sub>x</sub>C<sub>y</sub>O<sub>z</sub>H-based materials 1167
- six-transistor FinFET SRAM cell 1170
- small-angle cleaving technique (SACT) 477–478
- small-angle scattering approximation 83
- small-angle X-ray scattering (SAXS) 273
- small-diameter low-energy scanning Ar ion beams 490
- small organic molecules 1337
- smoothness term 863
- snapshot ring diffraction 328*f*
- Snell's law 504
- snorkel lens 618
- soft X-ray diffraction 444
- soft X-ray imaging methods, types 746
- soft X-ray microscopy
  - adsorption of human serum albumin (HSA), study of 774–775
  - chemical interactions at Co-NiO interface 774
  - chemical mapping technique 764–771
  - data analysis methods 764–771
  - 3D imaging (tomography) and 3D chemical mapping (spectrotomography) 775–777
  - ferromagnetic and antiferromagnetic domains, study of interactions 773–774
  - model of PS/PMMA thin film 766
  - multivariate statistical analysis (MSA) methods 771
  - polymer analysis 771–773
  - quantitative mapping 766–768
  - radiation damages 763–764
  - reviews 746
  - sample preparation issues 762–763
  - scanning yield techniques 757–763
  - selected applications 771–780
  - singular value decomposition (SVD) 765–766
  - *in situ* studies 777–780
  - surface topography and interfaces 773–775
  - synchrotron 747*t*–748*t*
  - unsupervised statistical analysis methods 768–771
- Soft X-rays and Extreme Ultraviolet Radiation, Principles and Applications* (David Attwood) 746
- soft X-ray undulator radiation 751

- solar-to-electricity conversion technology 1211
- soldering temperature-sensitive devices 324
- solid-state selective oxidation process 388
- space charge effects, on DTEM 313
- spatial coherence, of speckles 419–421
- spatial correlation, of speckle 428
- spatial-frequency-dependent phase-shifting properties, of lens 85
- spatial incoherence 57, 60
- spatial resolution 310
  - scanning probe microscopy (SPM) 501, 546–547
  - TiO<sub>2</sub> layer, layering of Au particles on 355
- spatiotemporal coherence 313
- sp<sup>2</sup>-carbon nanoforms 1021–1022
- speckle analysis, in diffraction patterns
  - of amorphous materials 406
  - of amorphous materials and disordered systems 434
  - in amorphous models of silicon clusters 415
  - Bragg reflections of 411–417
  - in calculated diffraction patterns of silicon structures 416f
  - causes 408–410
  - coherent interference 407
  - data blindness 434
  - definition 406–407
  - fluctuations in intensity 406
  - fringe spacing and 414
  - future directions 433–434
  - illumination coherence 417–421
  - intensity histograms 432f, 434
  - intensity variance 426
  - inversion problem 433–434
  - mean 428–430
  - measurement of 424–428
  - multidimensional data and 434
  - phase-retrieval methods 434
  - Poisson-type 415
  - scattered spherical wave amplitude and 408
  - from scattering of atom 412
  - shot noise 407
  - statistics 430–433
  - thermal diffuse scattering and 410
  - tomography and 434
  - variability of the distribution 425–426
  - variance 428–430
  - in X-ray and visible optics 408
- spectral signal-to-noise ratio (SSNR) method 260
- spectromicroscope for all relevant techniques (SMART) facility 752
- spectroscopic 3D 581
- spectroscopic ellipsometry 1163
- spectroscopic photoemission and low-energy electron microscope (SPELEEM) 694
- spherical aberration 2, 15, 336
- spherical aberration coefficient 55
- spherical aberration constant 301
- spherical aberration constant C<sub>s</sub> 67
- spherical-aberration-corrected lenses 2
- sp<sup>3</sup>-hybridized carbon atoms 1004
- spin-dependent QSE effect 699
- spin-polarized low-energy electron diffraction (SPLEED) 697
- spin-polarized low-energy electron microscopy (SPLEEM) 704
  - advantages of 705
  - areas of application 701–704
  - crystalline ferromagnetic materials, study of 698
  - electrostatic tetrode objective lens 700
  - exchange interaction 697–698
  - exchange-split band structure 698
  - illumination system 700
  - image of cobalt layer deposited on W(110) 703
  - inelastic scattering 700
  - in-plane magnetization 703
  - instrumentation 700–701
  - majority-spin and minority-spin bands 698–699
  - out-of-plane magnetization 703
  - polarization manipulator 700–701, 700f
  - quantum size effects (QSEs) 698
  - resolution 701
  - semiconductor cathodes 701
  - signal-to-noise ratio 701
  - specular intensity and exchange asymmetry 699f
  - spin-averaged information depth 699
  - spin-dependent band structure 698
  - spin-orbit interactions 697
  - spin reorientation transitions 702
  - theoretical foundations 697–700
- spin-polarized STM 549
- spiroids 1011–1012
- SPLEEM 6
- sputtering process 709–712
  - collision of particles 710
  - linear collisions 711
  - near-surface analysis 711
  - point of impact 711
  - primary particles, impact on 709, 710f



- SQUIDS 369  
 SR condition 30–31  
   – defect phase factor under 41  
 SRIM program 652  
 SrO atom column 90  
 SrRuO<sub>3</sub> 191  
 SrTiO<sub>3</sub> 191  
 stacking fault energy (SFE) 1072  
 stacking fault (SF) 40  
 stacking faults (SFs) 1072  
   – bright field (BF) contrast 1073  
 staining 1349–1350  
 standard deviation 286  
 standard error propagation theory 245  
 standard parameter space 26, 27*f*  
 starts 420  
 static electric dipole 500  
 static electrostatic SPMs 574  
 static SIMS 710–711  
 statistical Coulomb effects 313  
 statistical hypothesis testing 297  
 statistical model assessment methods  
   291–292  
 statistical parameter estimation theory 281,  
   298  
   – aim of 282–283  
   – description of observations 283–285  
 statistics for speckle  
   – for amorphous carbon 425*f*  
   – coherent illumination 432–433  
   – fit to a gamma distribution 432–433  
 stereo image matching 862  
 stereo matching 855  
 stereo microscopy 267  
 STM probes, modification of 549  
 Stobbs factor 95  
 Stokes theorem 173  
 Stokes' theorem 236  
 strain matrix 203  
 stray field effects 176–180  
   – above and below object 176–177  
   – lateral 180*f*  
   – in object-related field 179  
   – in object wave 179*f*  
   – on reference area 177–180  
   – on single domain magnetized finite cylinder  
     177  
 stress analysis 521  
 strontium titanate 579  
 strontium titanate (SrTiO<sub>3</sub>), NCSI of 87–88,  
   97*f*, 98–100  
   – amplitude contrast 90  
   – intensity values 98–101  
   – local intensity modulation 90  
   – optimal contrasts 98  
   – simulated images for 89*f*  
   – thickness series of images 98  
   – vs PCSI conditions 98–99  
   – WPO of 88  
   structure factors 76  
   structure matrix 23  
   STS spectrum 561  
   styrene network 273  
   sub-Angstrom range 673  
   subcellular electrophysiology 576  
   subtomogram averaging 1324–1325  
   subwavelength-resolution optical image  
     recording 506  
   superposition of Bloch waves 25  
   surface topography, study of 684  
   Swammerdam, Jan 1  
   switching processes, in nanoscale ring-shaped  
     magnetic elements 239  
   switching spectroscopy piezoresponse force  
     microscopy (SS-PFM) 581  
   synchrotron-based X-ray techniques 726  
   synchrotron radiation for illumination  
     (XPEEM) 694  
   synchrotron X-ray tomography 254  
   systematic hydrocarbon oxidation experiments  
     380  
   systematic row (SR) orientation 18
- t**  
 taper-free MG pillars 1138  
 tapping mode imaging, in liquid  
   environments 565  
 Tecnai F20-Cscorr TEM 190  
 TEM  
   – of a hexagonal prismatic seed 172  
   – hologram, recording of 155*f*  
   – point resolution of 161  
 TEM00 Gaussian mode lasers 804  
 temperature-dependent self-repair  
   mechanism 351  
 temperature measurements 520  
 temporal coherence, of speckles 418  
 temporal incoherence 57, 60  
 temporal resolution 310  
 ternary compounds 1274  
 tetragonal structure 892  
 theory of detecting evanescent waves, by  
   near-field microscopy 505  
 theory of diffraction of an aperture 502  
 theory of geometric calibration 857–860  
 theory of imaging 54–57, 162  
 theory of profilometric examinations 507  
 thermal annealing 663

- thermal atom factors 64
- thermal conductivity 521
- thermal diffuse scattering (TDS) 134, 262, 328, 410, 676
- thermal phonons 410
- thermal pulsing 804–806
- thermal SPM imaging 587–588
- thermal (white noise) excitation 552–553
- thermionic electron emission microscopy (TEEM) 681
- thermionic emission electron gun 13
- thermionic emission electron microscope 310
- thermoelastic properties, analyses of 518
- thickness-integrated image, of high-angle scattering 134
- third-order aberration corrector 111–112
- third-order aberrations 15
- third-order spherical aberration 84
- Thomas–Fermi atomic model 649
  - for the low-energy range 651
- Thomas–Fermi screening function 650
- three-dimensional field ion microscopy (3DFIM) 811–813
- three-dimensional imaging technique 3
- three-dimensional network (TRICE) 1363
- three-dimensional relocation profilometer stage 505
- three-stage physical vapor deposition processes 1231
- through focus series 61
- through-silicon-vias (TSVs) 1170
- Ti6Al4V 1088–1089
- Ti/CNT interface 1002
- Ti column 90
- tilted bright field 675
- tilted specimen yields 95
- tilt-induced displacement, of specimen 201
- time and space resolutions, in STM experiments 562–563
- time-averaged illumination 419
- time averaging, of reconstructed wave 157–159
- time-dependent amplitude 159
- time-dependent Schrödinger equation 75
- time-resolved diffraction experiments 327
- time-resolved electron microscopy 314
- time-resolved LEEM 6
- time-zero reference point, for experiments 326–327
- Ti<sub>2</sub>Nb<sub>10</sub>O<sub>29</sub> perovskite 63
  - unit cell of 68f
- Ti<sub>50</sub>Ni<sub>30</sub>Pd<sub>20</sub> alloy 1075–1077, 1076f
- Ti–Ni–Pd series 1073–1077
  - antiphase boundary (APB)-like defect 1085
- TiO<sub>2</sub> layer, layering of Au particles on 355–356
- tip cantilever system 528
- tip–contact junction 579
- tip-enhanced near-field optical microscopy (TENOM) 1049–1050
- tip-enhanced photoluminescence microscopy 1052
- tip-enhanced Raman scattering (TERS) mode 596
- tip-enhanced Raman spectroscopy (TERS) 1049–1050
- tip–surface capacitance gradient 575
- tip–surface electrostatic forces 574–575
- tip–surface impedance 577
- tip–surface junction conductance, in STM 557
- tip-tethered antibody 550
- Ti-rich subnanometer 384
- titanium zone axis pattern 17
- Titan TEM 193, 195f
- ToF-SIMS instrument 716, 719–721
  - of a foraminifera 730f
  - LMIG sources 720–721
  - maps 721
  - signal intensities 727
  - V 725
- Tomographic and Holographic Microscope Acquisition Software (THOMAS) 201
- tomography, holographic 171, 180, 199–202
  - pn-junction in Si-needle 204f
  - reconstruction of a GaAs/Al<sub>0.33</sub>Ga<sub>0.67</sub>As nanorod 203
- Tonomura, Akira 228
- Topografiner 542
- topography and recognition (TREC) imaging mode 550
- torsional resonance 574
- transfer function
  - flat 57
  - for incoherent imaging 133
  - in incoherent imaging 59
  - in real imaging 52–53
- transition-metal oxide perovskites 1189
- transition temperature mapping (TTM) 587
- transmission electron microscopy (TEM) 221, 345, 615
  - aberration-corrected 81
  - aberration correctors 14
  - Au nanoparticle, changes on 352
  - basic principles of 11
  - beam sensitivity 1351–1353

- bending modulus by electric-field-induced mechanical resonance 986–988
  - bright-field 271
  - bright field/dark field imaging 11
  - convergent beam electron diffraction (CBED) 11
  - crystallograph 1362–1372
  - current–voltage ( $I$ – $V$ ) characteristics 347
  - diffraction modes 11, 16–18
  - elastic and inelastic scattering processes 14
  - elastic scattering mechanisms and 125
  - electromigration processes 347, 348*f*
  - electron scattering in 17
  - electron trajectories in the presence of spherical aberration 16*f*
  - fabricating of images 14
  - first 11
  - formation of an interference pattern 228
  - Foucault imaging 222–223, 222*f*
  - Fourier transform of the object wave front 14–15
  - Fresnel imaging 222–223, 222*f*
  - with gas nanoreactors 353–356
  - general layout 12–14
  - of graphene 351–352
  - of heavy atoms 2
  - imaging modes 11, 16–17, 19
  - inelastic scattering mechanisms and 126
  - instrumentation 1344–1346
  - lenses and lens aberrations 14–16
  - with liquid nanoreactors 356–360
  - and measuring electrical properties 346–350
  - and measuring optical properties 360–362
  - MEMS-based heaters 350–353
  - morphological aspects 1354–1358
  - needle direction and position 347
  - nonround optical elements 14
  - objective lens 13–14, 14*f*
  - reciprocal lattice points 17
  - reciprocal lattice points, excitation of 17
  - reciprocity between STEM and 125–129
  - sample preparation techniques 473–494, 1346–1351
  - *in situ*, 346, 348*f*, 354, 375
  - structural aspects 1358–1362
  - trajectories of beams 18
  - transport imaging, of active device structures 577–579
  - transverse polarizations 805
  - transverse wave vector ( $K$ ) 118
  - trench technique 488
  - triple-walled carbon nanotubes (TWCNTs) 999
  - tripod polishing method 483–485, 492
  - 1,3,5-tris(4''-iodo-2'-biphenyl)benzene 1042
  - tungsten field emitters 420
  - tunnel-field effect transistors (TFETs) 1151
  - tunneling, into low conducting surfaces 562
  - tunneling electrons, energy of 504
  - twin-jet polishing technique 479
  - twinning induced plasticity (TWIP) steels 1071
  - two-beam CBED patterns 29–30
    - beam divergence 29
    - and crystal symmetry 32
    - for reflection of Ti 29–30, 30*f*
    - zone axis 32
  - two-beam orientation 18
  - two-beam orientation solution 26–30
    - for CBED pattern 29–30
    - for a centrosymmetric crystal 28
    - dimensionless quantities 26
    - field image intensities 26–27
    - negative excitation errors 26
    - positive excitation errors 26
    - for real and imaginary parts of eigenvalues 28, 29*f*
    - using Bloch wave formalism 28
    - using Bragg equation 28
  - two-beam system 664
  - two-dimensional EELS mapping 111
  - two-dimensional silicon nitride formation 688
  - two-dimensional transverse coordinate ( $R$ ) 118
  - two-dimensional X-ray data 1367
  - twofold astigmatism 96
  - two-level channeling model 94
- u**
- ultrafast/4D electron tomography 1037
  - ultrafast electron diffraction (UED) 311
  - ultrahigh-resolution imaging, prerequisite for 82
  - ultrahigh vacuum (UHV) technology 677
  - ultramicrotomy 485–486, 487*f*–488*f*, 493
  - ultramicrotomy methods 477
  - ultrasonic cutters 475
  - undulator-based STXM beamlines 755
  - undulator-based TXM 751
  - universal screening function 650
  - unwrapping of phase 161
- v**
- vacuum reference holograms 239
  - vanadium 326

- vanadyl pyrophosphate catalysts 388  
 van der Waals interaction 507, 999–1000  
 variable pressure scanning electron microscope (VPSEM) 617–618, 639  
 variance 286  
 Verwey transition 226  
 “virtual” optical system 153  
 visibility criterion 39  
 vitrification process 1348–1349  
 voltage modulation, of SPM 579  
 voltage modulation SPMs 574–583  
 volume spectroscopy 271  
 von Mises stress distribution 521
- w**
- water-window biological imaging 750  
 waveform generation laser, arbitrary 333–334  
 wavelength of an electron, nonrelativistic expression for 73  
 wave-optical image processing 153, 156  
 wave-particle duality, of quantum mechanics 407  
 WC powder 389  
 weak-beam dark field (WBDF) imaging 267–268, 269f, 882  
 weak-beam imaging 410  
 weak phase approximation 73, 458  
 weak phase object approximation (WPO) 84–85  
 – of strontium titanate (SrTiO<sub>3</sub>) 88  
 weak phase object approximation (WPOA) 409  
 weak phase object (WPO) 58  
 Weibull statistics (WS) 1143  
 Weickenmeier–Kohl atomic scattering factors, for neutral atoms 30  
 weighted backprojection (WBP) 257f  
 weighted simultaneous iterative reconstruction technique (WSIRT)-algorithm 202  
 Wheatstone bridge 519, 522  
 white-line ratio 389  
 Wiener filter 53  
 window technique 478  
 WKB approximation 174  
 Wollaston wire (Pr/Rh thermocouple) 587  
 wurtzite-structured ZnO 965  
 wurtzite (WZ) structure 1221–1222
- x**
- “X-FEG” electron gun 194  
 X-ray CDI 467  
 X-ray crystallography 65, 290  
 X-ray diffraction 48, 68–69, 438  
 x-ray diffraction (XRD) experiment 17  
 X-ray electrostatic forcemicroscopy (X-EFM) 1046  
 X-ray fluorescence 726  
 X-ray linear dichroism (XLD) 752  
 X-ray linear magnetic dichroic (XLMD) signal 774  
 X-ray magnetic circular dichroism (XMCD) 752  
 X-ray magnetic linear dichroism (XMLD) 752  
 X-ray photons 47  
 X-ray powder diffraction 295, 1366  
 X-ray reflectometry 1163  
 X-ray scanner 254  
 X-ray sensitive camera 746
- y**
- YAG-bicrystal material 490, 625  
 YBa<sub>2</sub>Cu<sub>4</sub>O<sub>8</sub> 67  
 Yb/Si specimen preparation 478  
 Young’s fringes 414  
 Young’s fringes with sunlight 420  
 Young’s modulus of individual SWNT 985–986  
 Young’s slits experiment 419  
 yttria-stabilized zirconia 581
- z**
- Zassenhaus theorem 23  
 Z-contrast imaging 298, 309, 629, 1089, 1213, 1215, 1217–1219, 1238, 1218f, 1221f, 1234f, 1239–1241, 1239f. *see also* scanning transmission electron microscope (STEM)  
 – dynamical diffraction in 134–135  
 – in modern times 109–113  
 – of single-layer boron nitride 115f  
 Zemplin tableau 60  
 zeolites 254  
 Zernike phase contrast 222  
 Zernike phase-contrast – conditions 84  
 Zernike phase plate 92–93  
 Zernike phase-shift plate 92  
 zero-bias conductance 561  
 zero padding 163  
 zeugmatography 254  
 Zewail, Ahmad 5  
 zinblende (ZB) CdTe films 1221–1224  
 zirconia/polymer nanocomposite 260  
 ZnO nanowires 962, 965–966  
 Zn Pc molecules 1360

- ZnS@CdSe core-shell nanoparticles 899
- zone axis case 30, 32
- zone axis CBED pattern 32
- zone axis diffraction pattern (ZADP) 17
- z-piezo 542
- ZP X-ray lens 752–754
  - diffraction-limited resolution of 755
  - Rayleigh criteria 755

